



# HT32F12365/HT32F12366/HT32F22366 Datasheet

**32-Bit Arm® Cortex®-M3 Microcontroller,  
up to 256 KB Flash and 128 KB SRAM with 1 MSPS ADC,  
USART, UART, SPI, I<sup>2</sup>C, I<sup>2</sup>S, MCTM, GPTM, BFTM, PDMA,  
SCI, CRC, RTC, WDT, AES, EBI, CSIF and USB2.0 FS**

Revision: V1.00 Date: November 07, 2017

[www.holtek.com](http://www.holtek.com)

## Table of Contents

<b>1</b>	<b>General Description</b>	<b>6</b>
<b>2</b>	<b>Features</b>	<b>7</b>
	Core	7
	On-chip Memory	7
	Flash Memory Controller – FMC	7
	Reset Control Unit – RSTCU	8
	Clock Control Unit – CKCU	8
	Power Management – PWRCU	8
	External Interrupt/Event Controller – EXTI	9
	Analog to Digital Converter – ADC	9
	Analog Comparator – CMP	9
	I/O Ports – GPIO	10
	Motor Control Timer – MCTM	10
	PWM Generation and Capture Timers – GPTM	11
	Basic Function Timer – BFTM	11
	Watchdog Timer – WDT	11
	Real Time Clock – RTC	12
	Inter-integrated Circuit – I <sup>2</sup> C	12
	Serial Peripheral Interface – SPI	12
	Universal Synchronous Asynchronous Receiver Transmitter – USART	13
	Universal Asynchronous Receiver Transmitter – UART	13
	Smart Card Interface – SCI	14
	Inter-IC Sound – I <sup>2</sup> S	14
	Cyclic Redundancy Check – CRC	14
	Peripheral Direct Memory Access – PDMA	15
	External Bus Interface – EBI	15
	Universal Serial Bus Device Controller – USB	16
	Advanced Encryption Standard – AES	16
	Secure Digital Input Output – SDIO	16
	CMOS Sensor Interface – CSIF (HT32F22366 only)	17
	Debug Support	17
	Package and Operation Temperature	17
<b>3</b>	<b>Overview</b>	<b>18</b>
	Device Information	18
	Block Diagram	19

Memory Map .....	20
Clock Structure .....	23
<b>4 Pin Assignment.....</b>	<b>24</b>
<b>5 Electrical Characteristics .....</b>	<b>34</b>
Absolute Maximum Ratings .....	34
Recommended DC Operating Conditions .....	34
On-Chip LDO Voltage Regulator Characteristics.....	34
Power Consumption .....	35
Reset and Supply Monitor Characteristics.....	36
External Clock Characteristics.....	37
Internal Clock Characteristics .....	38
PLL Characteristics.....	38
USB PLL Characteristics .....	39
Memory Characteristics .....	39
I/O Port Characteristics.....	39
ADC Characteristics .....	41
Comparator Characteristics .....	42
GPTM/MCTM Characteristics .....	43
I <sup>2</sup> C Characteristics .....	43
SPI Characteristics .....	44
I <sup>2</sup> S Characteristics .....	46
SDIO Characteristics .....	48
CSIF Characteristics.....	49
USB Characteristics.....	49
<b>6 Package Information .....</b>	<b>51</b>
SAW Type 46-pin (6.5mm×4.5mm) QFN Outline Dimensions.....	52
48-pin LQFP (7mm×7mm) Outline Dimensions.....	53
64-pin LQFP (7mm×7mm) Outline Dimensions.....	54
100-pin LQFP (14mm×14mm) Outline Dimensions.....	55

## List of Tables

Table 1. Features and Peripheral List .....	18
Table 2. Register Map .....	21
Table 3. Pin Assignment for 46-pin QFN, 48/64/100-pin LQFP Package .....	28
Table 4. Pin Description .....	31
Table 5. Absolute Maximum Ratings .....	34
Table 6. Recommended DC Operating Conditions .....	34
Table 7. LDO Characteristics .....	34
Table 8. Power Consumption Characteristics .....	35
Table 9. V <sub>DD</sub> Power Reset Characteristics .....	36
Table 10. LVD/BOD Characteristics .....	36
Table 11. High Speed External Clock (HSE) Characteristics .....	37
Table 12. Low Speed External Clock (LSE) Characteristics .....	37
Table 13. High Speed Internal Clock (HSI) Characteristics .....	38
Table 14. Low Speed Internal Clock (LSI) Characteristics .....	38
Table 15. PLL Characteristics .....	38
Table 16. USB PLL Characteristics .....	39
Table 17. Flash Memory Characteristics .....	39
Table 18. I/O Port Characteristics .....	39
Table 19. ADC Characteristics .....	41
Table 20. Comparator Characteristics .....	42
Table 21. GPTM/MCTM Characteristics .....	43
Table 22. I <sup>2</sup> C Characteristics .....	43
Table 23. SPI Characteristics .....	44
Table 24. I <sup>2</sup> S Characteristics .....	46
Table 25. SDIO Characteristics .....	48
Table 26. CSIF Electrical Characteristics .....	49
Table 27. USB DC Electrical Characteristics .....	49
Table 28. USB AC Electrical Characteristics .....	50

## List of Figures

Figure 1. Block Diagram .....	19
Figure 2. Memory Map.....	20
Figure 3. Clock Structure .....	23
Figure 4. 46-pin QFN Pin Assignment .....	24
Figure 5. 48-pin LQFP Pin Assignment.....	25
Figure 6. 64-pin LQFP Assignment.....	26
Figure 7. 100-pin LQFP Assignment.....	27
Figure 8. ADC Sampling Network Model .....	42
Figure 9. I <sup>2</sup> C Timing Diagrams .....	44
Figure 10. SPI Timing Diagrams – SPI Master Mode .....	45
Figure 11. SPI Timing Diagrams – SPI Slave Mode with CPHA=1 .....	46
Figure 12. Timing of I <sup>2</sup> S Master Mode .....	47
Figure 13. Timing of I <sup>2</sup> S Slave Mode .....	47
Figure 14. SDIO Default Mode .....	48
Figure 15. SDIO High-speed Mode .....	49
Figure 16. USB Signal Rise Time and Fall Time and Cross-Point Voltage ( $V_{CRS}$ ) Definition .....	50

# 1 General Description

These devices are high performance, low power consumption 32-bit microcontrollers based around an Arm® Cortex®-M3 processor core. The Cortex®-M3 is a next-generation processor core which is tightly coupled with Nested Vectored Interrupt Controller (NVIC), SysTick timer, and includes advanced debug support.

The devices operate at a frequency of up to 96 MHz with a Flash accelerator to obtain maximum efficiency. They provide up to 256 KB of embedded Flash memory for code/data storage and 128 KB of embedded SRAM memory for system operation and application program usage. A variety of peripherals, such as ADC, I<sup>2</sup>C, USART, UART, SPI, I<sup>2</sup>S, PDMA, GPTM, MCTM, SCI, EBI, CRC-16/32, AES-128/256, USB2.0 FS, SDIO, CSIF and SWJ-DP (Serial Wire and JTAG Debug Port), etc., are also implemented in the devices series. Several power saving modes provide the flexibility for maximum optimization between wakeup latency and power consumption, an especially important consideration in low power applications.

The above features ensure that the devices are suitable for use in a wide range of applications, especially in areas such as white goods application control, power monitors, alarm systems, consumer products, handheld equipment, data logging applications, motor control, fingerprint recognition and so on.

**arm** CORTEX

## 2 Features

### Core

- 32-bit Arm® Cortex®-M3 processor core
- Up to 96 MHz operating frequency
- Single-cycle multiplication and hardware division
- Integrated Nested Vectored Interrupt Controller (NVIC)
- 24-bit SysTick timer

The Cortex®-M3 processor is a general-purpose 32-bit processor core especially suitable for products requiring high performance and low power consumption microcontrollers. It offers many special features such as a Thumb-2 instruction set, hardware divider, low latency interrupt respond time, atomic bit-banding access and multiple buses for simultaneous accesses. The Cortex®-M3 processor is based on the ARMv7 architecture and supports both Thumb and Thumb-2 instruction sets.

### On-chip Memory

- 256 KB on-chip Flash memory for instruction/data and option storage
- Up to 128 KB on-chip SRAM
- Supports multiple boot modes

The Arm® Cortex®-M3 processor is structured using Harvard architecture which uses a separate bus structure to fetch instructions and load/store data. The instruction code and data are both located in the same memory address space but in different address ranges. The maximum address range of the Cortex®-M3 is 4 GB due to its 32-bit bus address width. Additionally, a pre-defined memory map is provided by the Cortex®-M3 processor to reduce the software complexity of repeated implementation for different device vendors. However, some regions are used by the Arm® Cortex®-M3 system peripherals. Refer to the Arm® Cortex®-M3 Technical Reference Manual for more information. Figure 2 shows the memory map of the HT32F12365/12366/22366 series of devices, including Code, SRAM, peripheral, and other pre-defined regions.

### Flash Memory Controller – FMC

- Flash accelerator for maximum efficiency
- 32-bit word programming with In System Programming Interface (ISP) and In Application Programming (IAP)
- Flash protection capability to prevent illegal access

The Flash Memory Controller, FMC, provides all the necessary functions and pre-fetch buffer for the embedded on-chip Flash Memory. Since the access speed of the Flash Memory is slower than the CPU, a wide access interface with a pre-fetch buffer and cache are provided for the Flash Memory in order to reduce the CPU waiting time which will cause CPU instruction execution delays. Flash Memory word program/page erase functions are also provided.

## Reset Control Unit – RSTCU

- Supply supervisor:
  - Power On Reset / Power Down Reset – POR/PDR
  - Brown-out Detector – BOD
  - Programmable Low Voltage Detector – LVD

The Reset Control Unit, RSTCU, has three kinds of reset, a power on reset, a system reset and an APB unit reset. The power on reset, known as a cold reset, resets the full system during power up. A system reset resets the processor core and peripheral IP components with the exception of the SWJ-DP controller. The resets can be triggered by an external signal, internal events and the reset generators.

## Clock Control Unit – CKCU

- External 4 to 16 MHz crystal oscillator
- External 32.768 kHz crystal oscillator
- Internal 8 MHz RC oscillator trimmed to  $\pm 2\%$  accuracy at 3.3 V operating voltage and 25°C operating temperature
- Internal 32 kHz RC oscillator
- Integrated system clock PLL
- Independent clock divider and gating bits for peripheral clock sources

The Clock Control unit, CKCU, provides a range of oscillator and clock functions. These include a High Speed Internal RC oscillator (HSI), a High Speed External crystal oscillator (HSE), a Low Speed Internal RC oscillator (LSI), a Low Speed External crystal oscillator (LSE), a Phase Lock Loop (PLL), a HSE clock monitor, clock prescalers, clock multiplexers, APB clock divider and gating circuitry. The clocks of the AHB, APB and Cortex®-M3 are derived from the system clock (CK\_SYS) which can come from the LSI, LSE, HSI, HSE or PLL. The Watchdog Timer and Real Time Clock (RTC) use either the LSI or LSE as their clock source. The maximum operating frequency of the system core clock (CK\_AHB) can be up to 96 MHz.

## Power Management – PWRCU

- Single  $V_{DD}$  power supply: 2.0 V to 3.6 V
- Integrated 1.5 V LDO regulator for CPU core, peripherals and memories power supply
- $V_{BAT}$  battery power supply for RTC and backup registers
- Three power domains:  $V_{DD}$ , 1.5V and Backup
- Four power saving modes: Sleep, Deep-Sleep1, Deep-Sleep2, Power-Down

Power consumption can be regarded as one of the most important issues for many embedded system applications. Accordingly the Power Control Unit, PWRCU, in these devices provides many types of power saving modes such as Sleep, Deep-Sleep1, Deep-Sleep2 and Power-Down mode. These operating modes reduce the power consumption and allow the application to achieve the best trade-off between the conflicting demands of CPU operating time, speed and power consumption.



## External Interrupt/Event Controller – EXTI

- Up to 16 EXTI lines with configurable trigger source and type
- All GPIO pins can be selected as EXTI trigger source
- Source trigger type includes high level, low level, negative edge, positive edge, or both edge
- Individual interrupt enable, wakeup enable and status bits for each EXTI line
- Software interrupt trigger mode for each EXTI line
- Integrated deglitch filter for short pulse blocking

The External Interrupt/Event Controller, EXTI, comprises 16 edge detectors which can generate a wake-up event or interrupt requests independently. Each EXTI line can also be masked independently.

## Analog to Digital Converter – ADC

- 12-bit SAR ADC engine
- Up to 1 Msps conversion rate
- Up to 16 external analog input channels
- Conversion range:  $V_{REF+} \sim V_{REF-}$

A 12-bit multi-channel ADC is integrated in the device. There are multiplexed channels, which include 16 external analog signal channels and 2 internal channels can be measured. If the input voltage is required to remain within a specific threshold window, an Analog Watchdog function will monitor and detect these signals. An interrupt will then be generated to inform the device that the input voltage is not within the preset threshold levels. There are three conversion modes to convert an analog signal to digital data. The ADC can be operated in one shot, continuous and discontinuous conversion modes.

## Analog Comparator – CMP

- Two rail-to-rail comparators
- Each comparator has configurable negative inputs used for flexible voltage selection
- Dedicated I/O pin or internal voltage reference provided by 6-bit scaler
- Programmable hysteresis
- Programming speed and consumption
- Comparator output can be output to I/O or to timers or ADC trigger inputs
- 6-bit scaler can be configurable to dedicated I/O for voltage reference
- Comparator has interrupt generation capability with wakeup MCU from Sleep or Deep Sleep modes through the EXTI controller

The two general purpose comparators (CMP) are implemented within the device. They can be configured either as standalone comparators or combined with the different kinds of peripheral IP. Each comparator is capable of asserting interrupts to the NVIC or wakeup the MCU Sleep or Deep Sleep modes through EXTI wakeup event management unit.

## I/O Ports – GPIO

- Up to 80 GPIOs
- Port A, B, C, D, E are mapped as 16 external interrupts – EXTI
- Almost I/O pins are configurable output driving current

There are up to 80 General Purpose I/O pins, GPIO, named from PA0 ~ PA15 to PE0 ~ PE15 for the implementation of logic input/output functions. Each of the GPIO ports has a series of related control and configuration registers to maximize flexibility and to meet the requirements of a wide range of applications.

The GPIO ports are pin-shared with other alternative functions to obtain maximum functional flexibility on the package pins. The GPIO pins can be used as alternative functional pins by configuring the corresponding registers regardless of the input or output pins.

The external interrupts on the GPIO pins of the device have related control and configuration registers in the External Interrupt Control Unit, EXTI.

## Motor Control Timer – MCTM

- Two 16-bit up, down, up/down auto-reload counters
- 16-bit programmable prescaler allowing division of the counter clock frequency by any factor between 1 and 65536
- Input Capture function
- Compare Match Output
- PWM waveform generation with edge aligned and center-aligned Counting Modes
- Single Pulse Mode Output
- Complementary Outputs with programmable dead-time insertion
- Encoder interface controller with two inputs using quadrature decoder
- Supports 3-phase motor control and hall sensor interface
- Brake input to force the timer's output signals into a reset or fixed condition

The Motor Control Timer consists of a single 16-bit up/down counter; four 16-bit CCRs (Capture/Compare Registers), single 16-bit counter-reload register (CRR), single 8-bit repetition counter and several control/status registers. It can be used for a variety of purposes including measuring the pulse widths of input signals or generating output waveforms such as compare match outputs, PWM outputs or complementary PWM outputs with dead-time insertion. The MCTM supports an Encoder interface controller to an incremental encoder with two inputs. The MCTM is capable of offering full functional support for motor control, hall sensor interfacing and brake input.

## PWM Generation and Capture Timers – GPTM

- Two 16-bit up, down, up/down auto-reload counters
- 16-bit programmable prescaler allowing dividing the counter clock frequency by any factor between 1 and 65536
- Input Capture function
- Compare Match Output
- PWM waveform generation with Edge-aligned and Center-aligned Counting Modes
- Single Pulse Mode Output
- Encoder interface controller with two inputs using quadrature decoder

The General Purpose Timer consists of one 16-bit up/down-counter, four 16-bit Capture/Compare Registers (CCRs), one 16-bit Counter Reload Register (CRR) and several control/status registers. They can be used for a variety of purposes including general time measurement, input signal pulse width measurement, output waveform generation such as single pulse generation, or PWM output generation. The GPTM supports an Encoder Interface using a decoder with two inputs.

## Basic Function Timer – BFTM

- Two 32-bit compare/match count-up counters - no I/O control features
- One shot mode – counting stops after a match condition
- Repetitive mode – restart counter after a match condition

The Basic Function Timer is a simple count-up 32-bit counter designed to measure time intervals and generate a one shot or repetitive interrupts. The BFTM operates in two functional modes, repetitive or one shot mode. In the repetitive mode the BFTM restarts the counter when a compare match event occurs. The BFTM also supports a one shot mode which forces the counter to stop counting when a compare match event occurs.

## Watchdog Timer – WDT

- 12-bit down counter with 3-bit prescaler
- Interrupt or reset event for the system
- Programmable watchdog timer window function
- Register write protection function

The Watchdog Timer is a hardware timing circuit that can be used to detect system failures due to software malfunctions. It includes a 12-bit count-down counter, a prescaler, a WDT counter value register, a WDT delta value register, interrupt related circuits, WDT operation control circuitry and a WDT protection mechanism. The Watchdog Timer can be operated in an interrupt mode or a reset mode. The Watchdog Timer will generate an interrupt or a reset when the counter counts down and reaches a zero value. If the software does not reload the counter value before a Watchdog Timer underflow occurs, an interrupt or a reset will be generated when the counter underflows. In addition, an interrupt or reset is also generated if the software reloads the counter when the counter value is greater than or equal to the WDT delta value. This means the counter must be reloaded within a limited timing window using a specific method. The Watchdog Timer counter can be stopped while the processor is in the debug mode. There is a register write protect function which can be enabled to prevent it from changing the Watchdog Timer configuration unexpectedly.

## Real Time Clock – RTC

- 32-bit up-counter with a programmable prescaler
- Alarm function
- Interrupt and Wake-up event

The Real Time Clock, RTC for short, includes an APB interface, a 32-bit count-up counter, a control register, a prescaler, a compare register and a status register. Most of the RTC circuits are located in the Backup Domain except for the APB interface. The APB interface is located in the  $V_{DD15}$  power domain. Therefore, it is necessary to be isolated from the ISO signal that comes from the power control unit when the  $V_{DD15}$  power domain is powered off, that is when the device enters the Power-Down mode. The RTC counter is used as a wakeup timer to generate a system resume signal from the Power-Down mode.

## Inter-integrated Circuit – I<sup>2</sup>C

- Supports both master and slave modes with a frequency of up to 1 MHz
- Provide an arbitration function and clock synchronization
- Supports 7-bit and 10-bit addressing modes and general call addressing
- Supports slave multi-addressing mode with maskable address

The I<sup>2</sup>C Module is an internal circuit allowing communication with an external I<sup>2</sup>C interface which is an industry standard two line serial interface used for connection to external hardware. These two serial lines are known as a serial data line, SDA, and a serial clock line, SCL. The I<sup>2</sup>C module provides three data transfer rates: (1) 100 kHz in the Standard mode, (2) 400 kHz in the Fast mode and (3) 1 MHz in the Fast mode plus mode. The SCL period generation register is used to setup different kinds of duty cycle implementations for the SCL pulse.

The SDA line which is connected directly to the I<sup>2</sup>C bus is a bi-directional data line between the master and slave devices and is used for data transmission and reception. The I<sup>2</sup>C module also has an arbitration detect function and clock synchronization to prevent situations where more than one master attempts to transmit data to the I<sup>2</sup>C bus at the same time.

## Serial Peripheral Interface – SPI

- Supports both master and slave mode
- Frequency of up to ( $f_{PCLK}/2$ ) MHz for master mode and ( $f_{PCLK}/3$ ) MHz for slave mode
- FIFO Depth: 8 levels
- Multi-master and multi-slave operation

The Serial Peripheral Interface, SPI, provides an SPI protocol data transmit and receive function in both master and slave mode. The SPI interface uses 4 pins, which are the serial data input and output lines MISO and MOSI, the clock line, SCK, and the slave select line, SEL. One SPI device acts as a master device which controls the data flow using the SEL and SCK signals to indicate the start of data communication and the data sampling rate. To receive a data byte, the streamed data bits are latched on a specific clock edge and stored in the data register or in the RX FIFO. Data transmission is carried out in a similar way but in a reverse sequence. The mode fault detection provides a capability for multi-master applications.

## Universal Synchronous Asynchronous Receiver Transmitter – USART

- Supports both asynchronous and clocked synchronous serial communication modes
- Asynchronous operating baud rate up to ( $f_{\text{PCLK}}/16$ ) MHz and synchronous operating rate up to ( $f_{\text{PCLK}}/8$ ) MHz
- Full duplex communication
- Fully programmable serial communication characteristics including:
  - Word length: 7, 8, or 9-bit character
  - Parity: Even, odd, or no-parity bit generation and detection
  - Stop bit: 1 or 2 stop bit generation
  - Bit order: LSB-first or MSB-first transfer
- Error detection: Parity, overrun and frame error
- Auto hardware flow control mode – RTS, CTS
- IrDA SIR encoder and decoder
- RS485 mode with output enable control
- FIFO Depth:  $16 \times 9$  bits for both receiver and transmitter

The Universal Synchronous Asynchronous Receiver Transceiver, USART, provides a flexible full duplex data exchange using synchronous or asynchronous transfer. The USART is used to translate data between parallel and serial interfaces, and is commonly used for RS232 standard communication. The USART peripheral function supports four types of interrupt including Line Status Interrupt, Transmitter FIFO Empty Interrupt, Receiver Threshold Level Reaching Interrupt and Time Out Interrupt. The USART module includes a 16-byte transmitter FIFO, (TX\_FIFO) and a 16-byte receiver FIFO (RX\_FIFO). The software can detect a USART error status by reading the Line Status Register, LSR. The status includes the type and the condition of transfer operations as well as several error conditions resulting from Parity, Overrun, Framing and Break events.

## Universal Asynchronous Receiver Transmitter – UART

- Asynchronous serial communication operating baud-rate up to ( $f_{\text{PCLK}}/16$ ) MHz
- Full duplex communication
- Fully programmable serial communication characteristics including:
  - Word length: 7, 8 or 9-bit character
  - Parity: Even, odd or no-parity bit generation and detection
  - Stop bit: 1 or 2 stop bit generation
  - Bit order: LSB-first or MSB-first transfer
- Error detection: Parity, overrun and frame error

The Universal Asynchronous Receiver Transceiver, UART, provides a flexible full duplex data exchange using asynchronous transfer. The UART is used to translate data between parallel and serial interfaces, and is commonly used for RS232 standard communication. The UART peripheral function supports Line Status Interrupt. The software can detect a UART error status by reading the Line Status Register, LSR. The status includes the type and the condition of transfer operations as well as several error conditions resulting from Parity, Overrun, Framing and Break events.

## Smart Card Interface – SCI

- Supports ISO 7816-3 standard
- Character mode
- Single transmit buffer and single receive buffer
- 11-bit ETU (elementary time unit) counter
- 9-bit guard time counter
- 24-bit general purpose waiting time counter
- Parity generation and checking
- Automatic character retry on parity error detection in transmission and reception modes

The Smart Card Interface is compatible with the ISO 7816-3 standard. This interface includes Card Insertion/Removal detection, SCI data transfer control logic and data buffers, internal Timer Counters and corresponding control logic circuits to perform all the necessary Smart Card operations. The Smart Card interface acts as a Smart Card Reader to facilitate communication with the external Smart Card. The overall functions of the Smart Card interface are controlled by a series of registers including control and status registers together with several corresponding interrupts which are generated to get the attention of the microcontroller for SCI transfer status.

## Inter-IC Sound – I<sup>2</sup>S

- Master or slave mode
- Mono and stereo
- I2S-justified, Left-justified, and Right-justified mode
- 8/16/24/32-bit sample size with 32-bit channel extended
- 8 × 32-bit Tx & Rx FIFO with PDMA supported
- 8-bit Fractional Clock Divider with rate control

The I<sup>2</sup>S is a synchronous communication interface that can be used as a master or slave to exchange data with other audio peripherals, such as ADCs or DACs. The I<sup>2</sup>S supports a variety of data formats. In addition to the stereo I2S-justified, Left-justified and Right-justified modes, there are mono PCM modes with 8/16/24/32-bit sample size. When the I<sup>2</sup>S operates in the master mode, then when using the fractional divider, it can provide an accurate sampling frequency output and support the rate control function and fine-tuning of the output frequency to avoid system problems caused by the cumulative frequency error between different devices.

## Cyclic Redundancy Check – CRC

- Supports CRC16 polynomial: 0x8005,  
 $X^{16}+X^{15}+X^2+1$
- Supports CCITT CRC16 polynomial: 0x1021,  
 $X^{16}+X^{12}+X^5+1$
- Supports IEEE-802.3 CRC32 polynomial: 0x04C11DB7,  
 $X^{32}+X^{26}+X^{23}+X^{22}+X^{16}+X^{12}+X^{11}+X^{10}+X^8+X^7+X^5+X^4+X^2+X+1$
- Supports 1's complement, byte reverse & bit reverse operation on data and checksum

- Supports byte, half-word & word data size
- Programmable CRC initial seed value
- CRC computation executed in 1 AHB clock cycle for 8-bit data and 4 AHB clock cycles for 32-bit data
- Supports PDMA to complete a CRC computation of a block of memory

The CRC calculation unit is an error detection technique test algorithm which is used to verify data transmission or storage data correctness. A CRC calculation takes a data stream or a block of data as input and generates a 16-bit or 32-bit output remainder. Ordinarily, a data stream is suffixed by a CRC code and used as a checksum when being sent or stored. Therefore, the received or restored data stream is calculated by the same generator polynomial as described above. If the new CRC code result does not match the one calculated earlier, that means data stream contains a data error.

## Peripheral Direct Memory Access – PDMA

- 12 channels with trigger source grouping
- 8/16/32-bit width data transfer
- Supports Address increment, decrement or fixed mode
- 4-level programmable channel priority
- Auto reload mode
- Supports trigger source:  
ADC, SPI, EBI, CRC, USART, UART, I<sup>2</sup>C, I<sup>2</sup>S, GPTM, MCTM, SCI, AES, SDIO and software request

The Peripheral Direct Memory Access controller, PDMA, moves data between the peripherals and the system memory on the AHB bus. Each PDMA channel has a source address, destination address, block length and transfer count. The PDMA can exclude the CPU intervention and avoid interrupt service routine execution. It improves system performance as the software does not need to join each data movement operation.

## External Bus Interface – EBI

- Programmable interface for various memory types
- Translate the AHB transactions into the appropriate external device protocol
- Memory bank regions and independent chip select control for each memory bank
- Programmable timings to support a wide range of devices
- Includes page read mode
- Automatic translation when the AHB transaction width and external memory interface width is different
- Write buffer to decrease the stalling of the AHB write burst transaction
- Multiplexed and non-multiplexed address and data line configurations
  - Up to 25 address lines
  - Up to 16-bit data bus width

The external bus interface is able to access external parallel interface devices such as SRAM, Flash and LCD modules. The interface is memory mapped into the internal address map of the



CPU. The data and address lines are multiplexed in order to reduce the number of pins required to connect to the external devices. The read/write timing of the bus can be adjusted to meet the timing specification of the external devices. Note the interface only supports asynchronous 8-bit or 16-bit bus interface.

## Universal Serial Bus Device Controller – USB

- Complies with USB 2.0 full-speed (12 Mbps) specification
- On-chip USB full-speed transceiver
- 1 control endpoint (EP0) for control transfer
- 3 single-buffered endpoints for bulk and interrupt transfer
- 4 double-buffered endpoints for bulk, interrupt and isochronous transfer
- 1024 bytes EP-SRAM used as the endpoint data buffers

The USB device controller is compliant with the USB 2.0 full-speed specification. There is one control endpoint known as Endpoint 0 and seven configurable endpoints. A 1024 bytes SRAM is used as the endpoint buffer. Each endpoint buffer size is programmable using corresponding registers, which provides maximum flexibility for various applications. The integrated USB full-speed transceiver helps to minimize the overall system complexity and cost. The USB functional block also contains the resume and suspend feature to meet the requirements of low-power consumption.

## Advanced Encryption Standard – AES

- Supports AES Encrypt / Decrypt Function
- Supports AES ECB/CBC/CTR mode
- Supports Key Size 128, 192 and 256 bits
- Supports 4 words Initial Vector for CBC and CTR mode
- 8 × 32 bits ( Each IN and OUT FIFO Capacity ) for 2 AES Data blocks
- Supports DMA Interface
- Supports Word Data Swap Function

The AES core supports encryption and decryption function. AES only supports 128 bits input data to do encryption or decryption. Hardware does not pad any bits of input data. Software need to do pad action at first.

## Secure Digital Input Output – SDIO

- Supports two different data bus modes: 1-bit (default) and 4-bit
- Supports two different speed modes: Normal speed (default) and High speed
- SD clock frequency of up to 48 MHz
- SPI mode and MMC stream mode not supported

The SDIO includes a command register, argument register, response registers, data buffer, timeout counter and error detection logic. The SDIO supports single block and multi-block data transfers and is compatible with the PDMA, minimizing processor intervention for large data transfers.



## CMOS Sensor Interface – CSIF (HT32F22366 only)

- Up to 2048 × 2048 input resolution
- Supports 8-bit YUV422 and Raw RGB formats
- Up to ( $f_{\text{HCLK}}/3$ ) MHz input pixel clock frequency
- Multi VSYNC and HSYNC settings for image capture
- Hardware window capture function
- Fractional hardware sub-sample function
- Dual FIFOs each with a capacity of 8 × 32 bits which can be read by the PDMA or CPU

The CMOS Sensor Interface, otherwise known as the CSIF, provides an interface for image capture from CMOS sensors. The device can be connected to the CMOS sensor directly using its CMOS Sensor Interface. The CSIF supports both Vertical SYNC and Horizontal SYNC modes for image capture implementation. The CSIF consists of window capture and sub-sampling functions together with dual FIFOs, each with a capacity of 8 × 32 bits, to store data which can be moved to the internal SRAM via the Peripheral Direct Memory Access circuitry, PDMA. The CSIF does not support image data conversion or decode but rather transfers the image data received from the CMOS sensor to the internal SRAM transparently.

## Debug Support

- Serial Wire or JTAG Debug Port SWJ-DP
- 6 instruction comparators and 2 literal comparators for hardware breakpoint or code / literal patches
- 4 comparators for hardware watchpoints
- 1-bit asynchronous trace for serial wire debug mode – TRACESWO

## Package and Operation Temperature

- 46-pin QFN, 48/64/100-pin LQFP package
- Operation temperature range: -40 °C to 85 °C

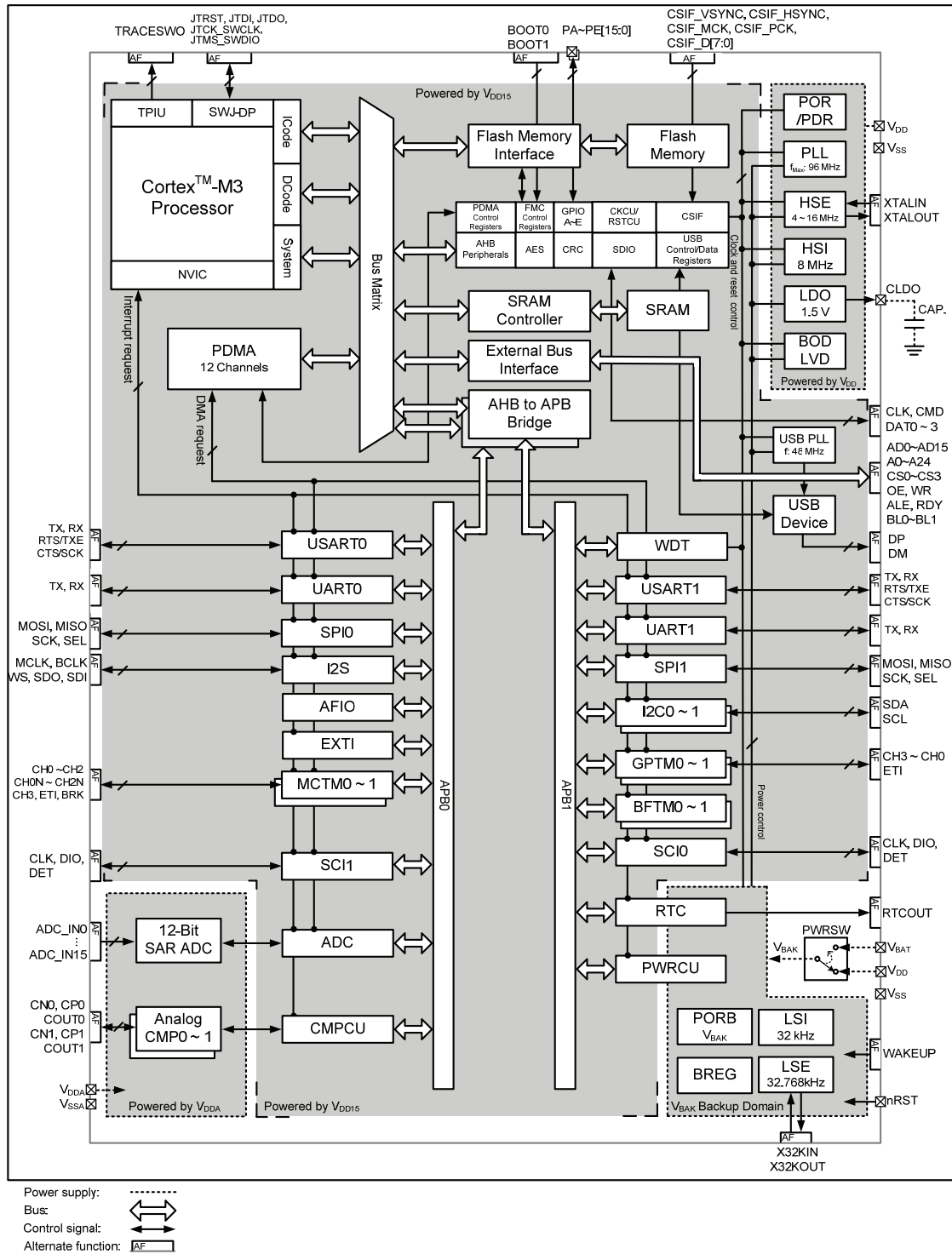
# 3 Overview

## Device Information

**Table 1. Features and Peripheral List**

Peripherals		HT32F12365	HT32F12366	HT32F22366
Main Flash (KB)		255	255	255
Option Bytes Flash (KB)		1	1	1
SRAM (KB)		64	128	128
Timers	MCTM	2		
	GPTM	2		
	BFTM	2		
	RTC	1		
	WDT	1		
Communication	CSIF	–	–	1
	USB	1		
	SCI	2		
	USART	2		
	UART	2		
	SPI	2		
	I2C	2		
	I2S	1		
PDMA		12 channels		
AES		1		
SDIO		1		
EBI		1		
CRC		1		
GPIO		Up to 80		
EXTI		16		
12-bit ADC		1		
Number of channels		Max. 16 Channels		
Comparator		2		
CPU frequency		Up to 96 MHz		
Operating voltage		2.0 V ~ 3.6 V		
Operating temperature		-40 °C ~ 85 °C		
Package		46-pin QFN, 48/64/100-pin LQFP		

## Block Diagram



Note: The AHB peripheral function, CSIF, is only available in the HT32F22366.

**Figure 1. Block Diagram**

## Memory Map

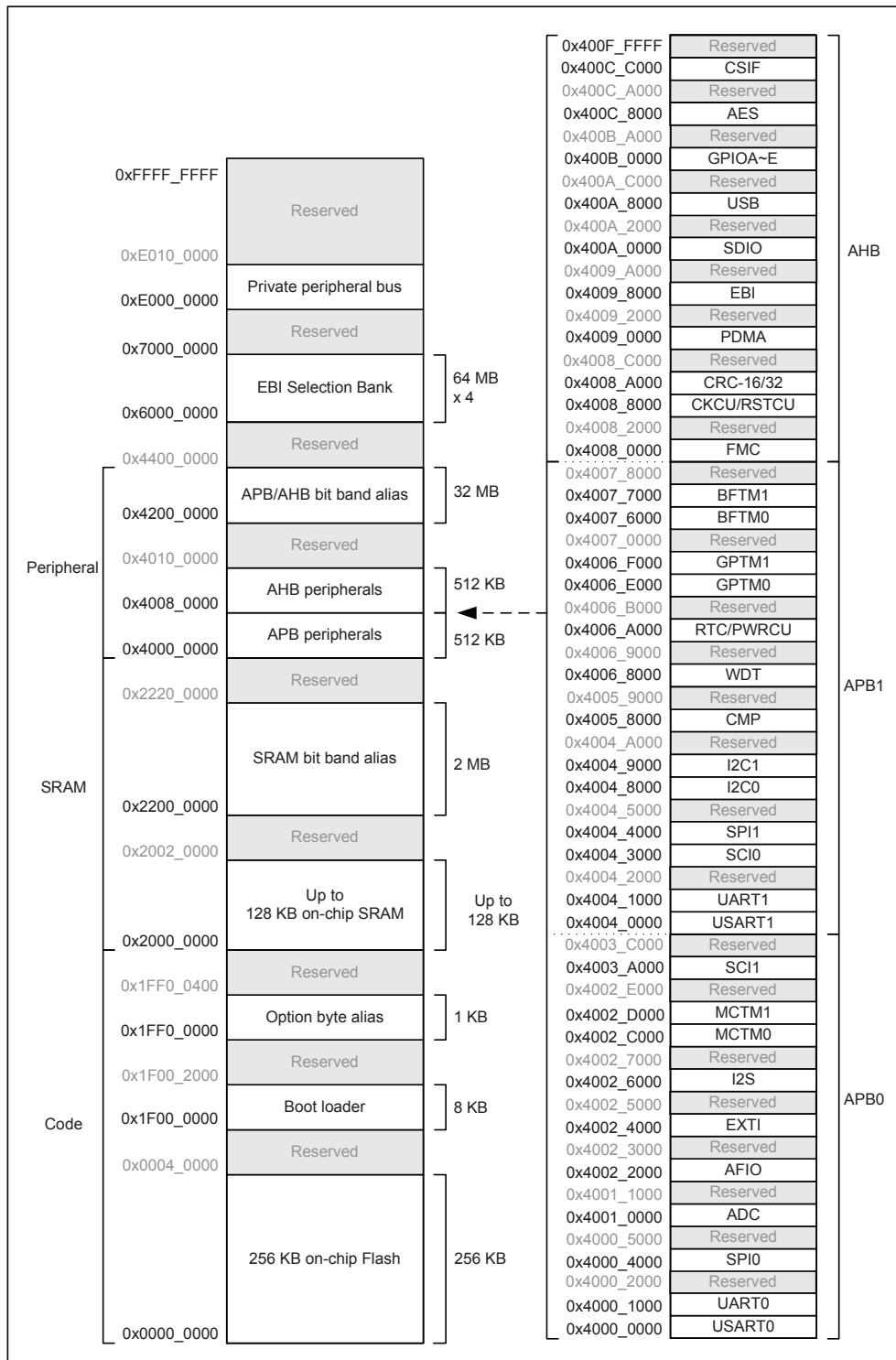


Figure 2. Memory Map

**Table 2. Register Map**

Start Address	End Address	Peripheral	Bus
0x4000_0000	0x4000_0FFF	USART0	APB0
0x4000_1000	0x4000_1FFF	UART0	
0x4000_2000	0x4000_3FFF	Reserved	
0x4000_4000	0x4000_4FFF	SPI0	
0x4000_5000	0x4001_9FFF	Reserved	
0x4001_0000	0x4001_0FFF	ADC	
0x4001_1000	0x4002_1FFF	Reserved	
0x4002_2000	0x4002_2FFF	AFIO	
0x4002_3000	0x4002_3FFF	Reserved	
0x4002_4000	0x4002_4FFF	EXTI	
0x4002_5000	0x4002_BFFF	Reserved	
0x4002_6000	0x4002_6FFF	I2S	
0x4002_7000	0x4002_BFFF	Reserved	
0x4002_C000	0x4002_CFFF	MCTM0	
0x4002_D000	0x4002_DFFF	MCTM1	
0x4002_E000	0x4003_AFFF	Reserved	
0x4003_A000	0x4003_AFFF	SCI1	
0x4003_C000	0x4003_FFFF	Reserved	
0x4004_0000	0x4004_0FFF	USART1	
0x4004_1000	0x4004_1FFF	UART1	
0x4004_2000	0x4004_2FFF	Reserved	
0x4004_3000	0x4004_3FFF	SCI0	
0x4004_4000	0x4004_4FFF	SPI1	
0x4004_5000	0x4004_7FFF	Reserved	
0x4004_8000	0x4004_8FFF	I2C0	
0x4004_9000	0x4004_9FFF	I2C1	
0x4004_A000	0x4005_7FFF	Reserved	
0x4005_8000	0x4005_8FFF	CMP	
0x4005_9000	0x4006_7FFF	Reserved	
0x4006_8000	0x4006_8FFF	WDT	
0x4006_9000	0x4006_9FFF	Reserved	
0x4006_A000	0x4006_AFFF	RTC/PWRCU	
0x4006_B000	0x4006_DFFF	Reserved	
0x4006_E000	0x4006_EFFF	GPTM0	
0x4006_F000	0x4006_FFFF	GPTM1	
0x4007_0000	0x4007_5FFF	Reserved	
0x4007_6000	0x4007_6FFF	BFTM0	
0x4007_7000	0x4007_7FFF	BFTM1	
0x4007_8000	0x4007_FFFF	Reserved	

Start Address	End Address	Peripheral	Bus
0x4008_0000	0x4008_1FFF	FMC	AHB
0x4008_2000	0x4008_7FFF	Reserved	
0x4008_8000	0x4008_9FFF	CKCU/RSTCU	
0x4008_A000	0x4008_BFFF	CRC-16/32	
0x4008_C000	0x4008_FFFF	Reserved	
0x4009_0000	0x4009_1FFF	PDMA Control Registers	
0x4009_2000	0x400C_BFFF	Reserved	
0x4009_8000	0x4009_9FFF	EBI Control Registers	
0x4009_A000	0x4009_FFFF	Reserved	
0x400A_0000	0x400A_1FFF	SDIO	
0x400A_2000	0x400A_7FFF	Reserved	
0x400A_8000	0x400A_9FFF	USB Control Registers	
0x400A_A000	0x400A_BFFF	USB SRAM	
0x400A_C000	0x400A_FFFF	Reserved	
0x400B_0000	0x400B_1FFF	GPIOA	
0x400B_2000	0x400B_3FFF	GPIOB	
0x400B_4000	0x400B_5FFF	GPIOC	
0x400B_6000	0x400B_7FFF	GPIOD	
0x400B_8000	0x400B_9FFF	GPIOE	
0x400B_A000	0x400C_7FFF	Reserved	
0x400C_8000	0x400C_9FFF	AES	
0x400C_A000	0x400C_BFFF	Reserved	
0x400C_C000	0x400C_DFFF	CSIF	
0x400C_E000	0x400F_FFFF	Reserved	

## Clock Structure

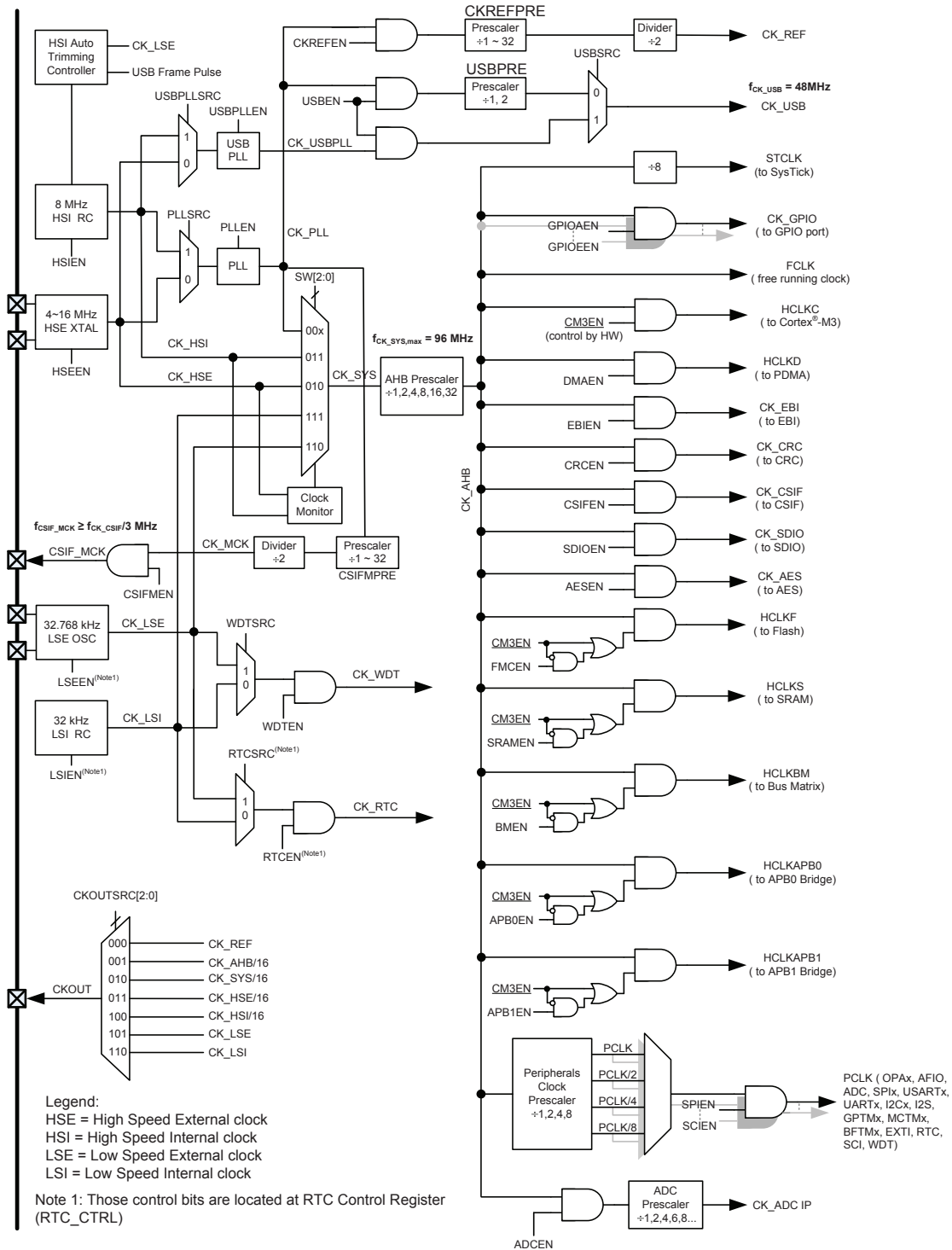


Figure 3. Clock Structure

# 4 Pin Assignment

**HT32F12365/12366/22366**  
**46 QFN-A**

		PA0	VSSA	VDDA	PB11	PB10	PB9	PB8	PB7	PB6	PB5	PB4	PB3	PB2	VSS_2	AF0 (Default)						
AF0 (Default)	○	33V	AP	AP	33V	33V	33V	33V	33V	33V	33V	33V	33V	33V	P33	AF0 (Default)	AF0 (Default)	AF1				
PA1	1	33V	P33 3.3 V Digital Power Pad AP 3.3 V Analog Power Pad P15 1.5 V Power Pad 33V 3.3 V Digital & Analog IO Pad 33V 3.3 V Digital I/O Pad USB USB PHY Pad BAK Backup Domain Pad VSS													P33	32	VDD_2				
PA2	2	33V														33V	31	PB1				
PA3	3	33V														33V	30	PB0				
PA4	4	33V														33V	29	JTRST	PA15			
PA5	5	33V														33V	28	JTDI	PA14			
PA6	6	33V														33V	27	JTMS/ SWDIO	PA13			
PA7	7	33V														33V	26	JTCK/ SWCLK	PA12			
USBDM/ PB12	8	USB														33V	25	JTDO	PA11			
USBDM/ PB12	9	USB														33V	24	PA10				
		P15	P33	P33	BAK 33V	BAK P33	BAK 33V	BAK 33V	BAK 33V	33V	33V	33V	33V	33V	33V							
		10	11	12	13	14	15	16	17	18	19	20	21	22	23							
		CLDO	VDD_1	VSS_1	nRST	VBAT	X32KIN	X32KOUT	RTCOUT	XTALIN	XTALOUT	PD4	PD5	PA8_ BOOT0	PA9_ BOOT1	AF0 (Default)						
															AF0 (Default)	AF1						
																		PC13	PC14	PC15	PB14	PB15

Pin Assignment

**Figure 4. 46-pin QFN Pin Assignment**





**HT32F12365/12366/22366  
 64 LQFN-A**

		VSSA	VDDA	PB11	PB10	PB9	PB8	PB7	PB6	VSS_4	VDD_4	PC8	PC7	PB5	PB4	PB3	PB2	AF0 (Default)			AF0 (Default)	AF1	
AF0 (Default)	○	64	63	62	61	60	59	58	57	56	55	54	53	52	51	50	49						
		AP	AP	33V	33V	33V	33V	33V	33V	P33	P33	33V	33V	33V	33V	33V	33V						
PA0	1	33V																33V	48	PC6			
PA1	2	33V																33V	47	PC5			
PA2	3	33V																33V	46	PC4			
PA3	4	33V																33V	45	PB1			
PA4	5	33V																33V	44	PB0			
PA5	6	33V																P33	43	VSS_2			
PA6	7	33V																P33	42	VDD_2			
PA7	8	33V																33V	41	JTRST	PA15		
VDD_3	9	P33																33V	40	JTDI	PA14		
VSS_3	10	P33																33V	39	JTMS/ SWDIO	PA13		
PC9	11	33V																33V	38	JTCK/ SWCLK	PA12		
PC10	12	33V																33V	37	JTDO	PA11		
PC11	13	33V																33V	36	PA10			
PC12	14	33V																33V	35	PA9_ BOOT1			
USBDM/ PB12	15	USB																33V	34	PA8_ BOOT0			
USBDP/ PB13	16	USB																33V	33	PC3			
		P15	P33	P33	BAK 33V	BAK P33	BAK 33V	BAK 33V	BAK 33V	33V	33V	33V	33V	33V	33V	33V	33V						
		17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32						
		CLDO	VDD_1	VSS_1	nRST	VBAT	X32KIN	X32KOUT	RTCOUT	PD0	XTALIN	XTALOUT	PD4	PD5	PC0	PC1	PC2						
							PC13	PC14	PC15		PB14	PB15											

**Legend:**

- P33 3.3 V Digital Power Pad
- AP 3.3 V Analog Power Pad
- P15 1.5 V Power Pad
- 33V 3.3 V Digital & Analog I/O Pad
- 33V 3.3 V Digital I/O Pad
- USB USB PHY Pad
- BAK Backup Domain Pad

Pin Assignment

**Figure 6. 64-pin LQFP Assignment**

HT32F12365/12366/22366  
 100 LQFN-A

		VSSA	VREF-	VREF+	VDDA	PB11	PB10	PB9	PB8	PB7	PB6	PE7	PE6	PE5	PE4	VSS_4	VDD_4	PE3	PE2	PE1	PC8	PC7	PB5	PB4	PB3	PB2	AF0 (Default)	AF1		
AF0 (Default)	○	100	99	98	97	96	95	94	93	92	91	90	89	88	87	86	85	84	83	82	81	80	79	78	77	76	AF0 (Default)	AF1		
		AP	AP	AP	AP	33V	33V	33V	33V	33V	33V	33V	33V	33V	33V	P33	P33	33V	33V	33V	33V	33V	33V	33V	33V	33V				
PA0	1	33V																								33V	75	PE0		
PA1	2	33V																								33V	74	PD15		
PA2	3	33V																								33V	73	PD14		
PA3	4	33V																								33V	72	PD13		
PA4	5	33V																								33V	71	PD12		
PA5	6	33V																								33V	70	PD11		
PA6	7	33V																								33V	69	PD10		
PA7	8	33V																								33V	68	PD9		
PE8	9	33V																								33V	67	PC6		
PE9	10	33V																								33V	66	PC5		
PE10	11	33V																								33V	65	PC4		
PE11	12	33V																								33V	64	PB1		
PE12	13	33V																								33V	63	PB0		
VDD_3	14	P33																								P33	62	VSS_2		
VSS_3	15	P33																								P33	61	VDD_2		
PC9	16	33V																								33V	60	JTRST	PA15	
PC10	17	33V																								33V	59	JTDI	PA14	
PC11	18	33V																								33V	58	JTMS/ SWDIO	PA13	
PC12	19	33V																								33V	57	JTCK/ SWCLK	PA12	
PD6	20	33V																								33V	56	JTDO	PA11	
PB12	21	33V																								33V	55	PA10		
USBDM	22	USB																								33V	54	PA9 BOOT1		
USBDP	23	USB																								33V	53	PA8 BOOT0		
PB13	24	33V																								33V	52	PD8		
NC	25																									33V	51	PD7		
			P15	P33	P33	BAK 33V	BAK P33	BAK 33V	BAK 33V	BAK 33V	33V	33V	33V	33V	33V	33V	33V	P33	P33	33V	33V	33V	33V	33V	33V	33V	33V	33V	33V	
			26	27	28	29	30	31	32	33	34	35	36	37	38	39	40	41	42	43	44	45	46	47	48	49	50			
			CLDO	VDD_1	VSS_1	rRST	VBAT	X32KIN	X32KOUT	RTCOU	PD0	PE13	PE14	PE15	XTALIN	XTALOUT	VDD_5	VSS_5	PD1	PD2	PD3	PD4	PD5	PC0	PC1	PC2	PC3	AF0 (Default)	AF1	

Pin Assignment

Figure 7. 100-pin LQFP Assignment

**Table 3. Pin Assignment for 46-pin QFN, 48/64/100-pin LQFP Package**

Package				Alternate Function Number															
100 LQFP	64 LQFP	48 LQFP	46 QFN	AF0 System Default	AF1 GPIO	AF2 ADC	AF3 CMP	AF4 MCTM /GPTM	AF5 SPI	AF6 USART /UART	AF7 I <sup>2</sup> C	AF8 SCI	AF9 EBI	AF10 I <sup>2</sup> S	AF11 SDIO	AF12 CSIF	AF13 N/A	AF14 N/A	AF15 System Other
1	1	1	46	PA0		ADC_IN0		GT1_CH0	SPI1_SCK	USR0_RTS	I2C1_SCL	SCI0_CLK		I2S_WS		CSIF_D0			
2	2	2	1	PA1		ADC_IN1		GT1_CH1	SPI1_MOSI	USR0_CTS	I2C1_SDA	SCI0_DIO		I2S_BCLK	SD_DAT1	CSIF_D1			
3	3	3	2	PA2		ADC_IN2		GT1_CH2	SPI1_MISO	USR0_TX				I2S_SDO	SD_DAT2	CSIF_D2			
4	4	4	3	PA3		ADC_IN3		GT1_CH3	SPI1_SEL	USR0_RX				I2S_SDI	SD_DAT3	CSIF_D3			
5	5	5	4	PA4		ADC_IN4		GT0_CH0	SPI0_SCK	USR1_TX	I2C0_SCL	SCI1_CLK			SD_CMD	CSIF_D4			
6	6	6	5	PA5		ADC_IN5		GT0_CH1	SPI0_MOSI	USR1_RX	I2C0_SDA	SCI1_DIO			SD_CLK	CSIF_D5			
7	7	7	6	PA6		ADC_IN6		GT0_CH2	SPI0_MISO	USR1_RTS		SCI1_DET			SD_DAT0	CSIF_D6			
8	8	8	7	PA7		ADC_IN7		GT0_CH3	SPI0_SEL	USR1_CTS				I2S_MCLK		CSIF_D7			
9				PE8		ADC_IN8			SPI1_SEL	USR0_RTS						CSIF_HSYNC			
10				PE9		ADC_IN9			SPI1_SCK	USR0_CTS						CSIF_VSYNC			
11				PE10		ADC_IN10			SPI1_MOSI	USR0_TX						CSIF_PCK			
12				PE11		ADC_IN11			SPI1_MISO	USR0_RX						CSIF_MCK			
13				PE12		ADC_IN12													
14	9	9		VDD_3															
15	10	10	EP*	VSS_3															
16	11			PC9		ADC_IN13		GT0_CH0	SPI1_SEL	UR0_TX	I2C1_SCL				SD_DAT0	CSIF_HSYNC			
17	12			PC10		ADC_IN14		GT0_CH1	SPI1_SCK	UR0_RX	I2C1_SDA				SD_DAT1	CSIF_VSYNC			
18	13			PC11		ADC_IN15		GT0_CH2	SPI1_MOSI						SD_DAT2	CSIF_PCK			
19	14			PC12				GT0_CH3	SPI1_MISO						SD_DAT3	CSIF_MCK			
20				PD6				GT0_ET1					EBI_NRDY						
21	15	11	8	PB12				MT1_CH2		USR0_TX	I2C0_SCL					CSIF_D7			
22	15	11	8	USBDM															
23	16	12	9	USBDP															
24	16	12	9	PB13				MT1_CH2N		USR0_RX	I2C0_SDA					CSIF_D6			
25				NC															
26	17	13	10	CLDO															
27	18	14	11	VDD_1															
28	19	15	12	VSS_1															
29	20	16	13	nRST															
30	21	17	14	VBAT															
31	22	18	15	X32KIN	PC13														
32	23	19	16	X32KOUT	PC14														
33	24	20	17	RTCOUT	PC15														WAKEUP
34	25			PD0				MT1_ET1			I2C0_SDA		EBI_A18	I2S_SDI	SD_CMD				
35				PE13							I2C0_SCL		EBI_A19	I2S_MCLK					
36				PE14				GT1_ET1					EBI_A20	I2S_WS					
37				PE15				GT1_CH0		UR0_TX			EBI_A21						

Pin Assignment

Package				Alternate Function Number																
100 LQFP	64 LQFP	48 LQFP	46 QFN	AF0 System Default	AF1 GPIO	AF2 ADC	AF3 CMP	AF4 MCTM /GPTM	AF5 SPI	AF6 USART /UART	AF7 I <sup>2</sup> C	AF8 SCI	AF9 EBI	AF10 I <sup>2</sup> S	AF11 SDIO	AF12 CSIF	AF13 N/A	AF14 N/A	AF15 System Other	
38	26	21	18	XTALIN	PB14															
39	27	22	19	XTALOUT	PB15															
40				VDD_5																
41				VSS_5																
42				PD1				GT1_CH1		UR0_RX			EBI_A22	I2S_BCLK						
43				PD2				GT1_CH2					EBI_A23	I2S_SDO						
44				PD3				GT1_CH3					EBI_A24	I2S_SDI						
45	28	23	20	PD4				MT1_CH0	SPI0_SEL		I2C1_SCL	SCI1_CLK	EBI_A16	I2S_MCLK	SD_CLK	CSIF_D5				
46	29	24	21	PD5				MT1_CH0N	SPI0_SCK		I2C1_SDA	SCI1_DIO	EBI_A17		SD_CMD	CSIF_D4				
47	30			PC0				GT1_CH0	SPI1_SEL				EBI_AD13	I2S_WS	SD_DAT1					
48	31			PC1				GT1_CH1	SPI1_SCK				EBI_AD14	I2S_BCLK	SD_DAT2					
49	32			PC2				GT1_CH2	SPI1_MOSI	UR1_TX	I2C0_SCL		EBI_AD15	I2S_SDO	SD_DAT3					
50	33			PC3				GT1_CH3	SPI1_MISO	UR1_RX	I2C0_SDA	SCI1_DET	EBI_CS3	I2S_SDI	SD_DAT0					
51				PD7							I2C1_SCL		EBI_A2							
52				PD8							I2C1_SDA		EBI_A0							
53	34	25	22	PA8_BOOT0						USR0_TX		SCI1_CLK		I2S_MCLK						CKOUT
54	35	26	23	PA9_BOOT1					SPI0_MOSI			SCI1_DIO	EBI_A1	I2S_WS						
55	36	27	24	PA10				MT1_CH1		USR0_RX		SCI0_DET			SD_DAT0	CSIF_D7				
56	37	28	25	JTDO	PA11			MT1_CH1N	SPI0_MISO			SCI1_DET	EBI_A0	I2S_MCLK						TRACESWO
57	38	29	26	JTCK/SWCLK	PA12															
58	39	30	27	JTMS/SWDIO	PA13															
59	40	31	28	JTDI	PA14			MT0_CH0	SPI1_SEL	USR1_TX		SCI0_CLK	EBI_AD0				CSIF_HSYNC			
60	41	32	29	JTRST	PA15			MT0_CH0N	SPI1_SCK	USR1_RX		SCI0_DIO	EBI_AD1				CSIF_VSYNC			
61	42			VDD_2																
62	43			VSS_2																
63	44	33	30	PB0				MT0_CH1	SPI1_MOSI	USR0_TX	I2C0_SCL		EBI_AD2				CSIF_PCK			
64	45	34	31	PB1				MT0_CH1N	SPI1_MISO	USR0_RX	I2C0_SDA		EBI_AD3				CSIF_MCK			
65	46			PC4				MT1_CH2		USR1_RTS		SCI0_CLK	EBI_AD10		SD_CLK					
66	47			PC5				MT1_CH2N		USR1_CTS		SCI0_DIO	EBI_AD11		SD_CMD					
67	48			PC6				MT1_CH3				SCI0_DET	EBI_AD12		SD_DAT0					
68				PD9					SPI0_SEL				EBI_A3							
69				PD10					SPI0_SCK				EBI_A4							
70				PD11					SPI0_MOSI				EBI_A5							
71				PD12					SPI0_MISO				EBI_A6							
72				PD13					SPI1_SEL				EBI_A7							

Package				Alternate Function Number																
100 LQFP	64 LQFP	48 LQFP	46 QFN	AF0 System Default	AF1 GPIO	AF2 ADC	AF3 CMP	AF4 MCTM /GPTM	AF5 SPI	AF6 USART /UART	AF7 I <sup>2</sup> C	AF8 SCI	AF9 EBI	AF10 I <sup>2</sup> S	AF11 SDIO	AF12 CSIF	AF13 N/A	AF14 N/A	AF15 System Other	
73				PD14					SPI1_SCK				EBI_A8							
74				PD15					SPI1_MOSI				EBI_A9							
75				PE0					SPI1_MISO				EBI_A10							
		35	32	VDD_2																
		36	33	VSS_2																
76	49	37	34	PB2				MT0_CH2	SPI0_SEL	UR0_TX			EBI_AD4			CSIF_D0			CKIN	
77	50	38	35	PB3				MT0_CH2N	SPI0_SCK	UR0_RX			EBI_AD5			CSIF_D1				
78	51	39	36	PB4				MT0_BRK	SPI0_MOSI	UR1_TX			EBI_AD6			CSIF_D2				
79	52	40	37	PB5				MT1_BRK	SPI0_MISO	UR1_RX			EBI_AD7			CSIF_D3				
80	53			PC7				MT0_CH3			I2C0_SCL		EBI_AD8		SD_CMD					
81	54			PC8				MT0_ETI			I2C0_SDA		EBI_AD9		SD_CLK					
82				PE1				MT1_CH0		USR1_TX		SCI0_CLK	EBI_A11							
83				PE2				MT1_CH0N				SCI0_DIO	EBI_A12							
84				PE3				MT1_CH1					EBI_A13							
85	55			VDD_4																
86	56			VSS_4																
87				PE4				MT1_CH1N			I2C1_SCL		EBI_A14		SD_DAT0					
88				PE5				MT1_CH2		USR1_RX	I2C1_SDA		EBI_A15		SD_DAT1					
89				PE6				MT1_CH2N		USR1_RTS			EBI_BL0	I2S_BCLK	SD_DAT2					
90				PE7				MT1_BRK		USR1_CTS			EBI_BL1	I2S_MCLK	SD_DAT3					
91	57	41	38	PB6			CN0	MT1_CH0	SPI1_SEL	UR1_TX			EBI_OE	I2S_MCLK		CSIF_D4				
92	58	42	39	PB7			CP0	MT1_CH0N	SPI1_SCK				EBI_CS0			CSIF_D5				
93	59	43	40	PB8			COUT0		SPI1_MOSI	UR1_RX			EBI_WE			CSIF_D6				
94	60	44	41	PB9			CN1	MT1_CH2	SPI1_MISO	UR0_TX		SCI1_CLK	EBI_ALE	I2S_BCLK	SD_DAT1	CSIF_D7				
95	61	45	42	PB10			CP1	MT1_CH2N			I2C1_SCL	SCI1_DET	EBI_CS1	I2S_SDO	SD_DAT2					
96	62	46	43	PB11			COUT1	MT1_CH3		UR0_RX	I2C1_SDA	SCI1_DIO	EBI_CS2	I2S_SDI	SD_DAT3					
97	63	47	44	VDDA																
98	63	47	44	VREF+																
99	64	48	45	VREF-																
100	64	48	45	VSSA																

Note: The EP is meant the exposed pad of the QFN package.

**Table 4. Pin Description**

Pin Number				Pin Name	Type (1)	I/O Structure (2)	Output Driving	Description
100 LQFP	64 LQFP	48 LQFP	46 QFN					Default Function (AF0)
1	1	1	46	PA0	AI/O	33V	4/8/12/16 mA	PA0
2	2	2	1	PA1	AI/O	33V	4/8/12/16 mA	PA1
3	3	3	2	PA2	AI/O	33V	4/8/12/16 mA	PA2
4	4	4	3	PA3	AI/O	33V	4/8/12/16 mA	PA3
5	5	5	4	PA4	AI/O	33V	4/8/12/16 mA	PA4
6	6	6	5	PA5	AI/O	33V	4/8/12/16 mA	PA5
7	7	7	6	PA6	AI/O	33V	4/8/12/16 mA	PA6
8	8	8	7	PA7	AI/O	33V	4/8/12/16 mA	PA7
9				PE8	AI/O	33V	4/8/12/16 mA	PE8
10				PE9	AI/O	33V	4/8/12/16 mA	PE9
11				PE10	AI/O	33V	4/8/12/16 mA	PE10
12				PE11	AI/O	33V	4/8/12/16 mA	PE11
13				PE12	AI/O	33V	4/8/12/16 mA	PE12
14	9	9		VDD_3	P	—	—	Voltage for digital I/O
15	10	10	EP	VSS_3	P	—	—	Ground reference for digital I/O
16	11			PC9	AI/O	33V	4/8/12/16 mA	PC9
17	12			PC10	AI/O	33V	4/8/12/16 mA	PC10
18	13			PC11	AI/O	33V	4/8/12/16 mA	PC11
19	14			PC12	AI/O	33V	4/8/12/16 mA	PC12
20				PD6	AI/O	33V	4/8/12/16 mA	PD6
21	15	11	8	PB12	I/O	33V	4/8/12/16 mA	PB12
22	15	11	8	USBDM	AI/O	—	—	USB Differential data bus conforming to the Universal Serial Bus standard
23	16	12	9	USBDP	AI/O	—	—	USB Differential data bus conforming to the Universal Serial Bus standard
24	16	12	9	PB13	I/O	33V	4/8/12/16 mA	PC7
25				NC	—	—	—	NC
26	17	13	10	CLDO	P	—	—	Core power LDO 1.5V output. It is recommended to connect a 4.7uF capacitor as close as possible between this pin and VSS_1.
27	18	14	11	VDD_1	P	—	—	Voltage for digital I/O
28	19	15	12	VSS_1	P	—	—	Ground reference for digital I/O
29	20	16	13	nRST	I(BK)	33V_PU	—	External reset pin and external wakeup pin in the Power-Down mode
30	21	17	14	VBAT	P	—	—	Battery power input for the backup domain
31	22	18	15	PC13(4)	AI/O(BK)	33V	< 2 mA	X32KIN
32	23	19	16	PC14(4)	AI/O(BK)	33V	< 2 mA	X32KOUT
33	24	20	17	PC15(4)	I/O(BK)	33V	< 2 mA	RTCOUT
34	25			PD0	I/O	33V	4/8/12/16 mA	PD0
35				PE13	I/O	33V	4/8/12/16 mA	PE13
36				PE14	I/O	33V	4/8/12/16 mA	PE14
37				PE15	I/O	33V	4/8/12/16 mA	PE15

Pin Assignment

Pin Number				Pin Name	Type (1)	I/O Structure (2)	Output Driving	Description
100 LQFP	64 LQFP	48 LQFP	46 QFN					Default Function (AF0)
38	26	21	18	PB14	AI/O	33V	4/8/12/16 mA	XTALIN
39	27	22	19	PB15	AI/O	33V	4/8/12/16 mA	XTALOUT
40				VDD_5	P	—	—	Voltage for digital I/O
41				VSS_5	P	—	—	Ground reference for digital I/O
42				PD1	I/O	33V	4/8/12/16 mA	PD1
43				PD2	I/O	33V	4/8/12/16 mA	PD2
44				PD3	I/O	33V	4/8/12/16 mA	PD3
45	28	23	20	PD4	I/O	33V	4/8/12/16 mA	PD4
46	29	24	21	PD5	I/O	33V	4/8/12/16 mA	PD5
47	30			PC0	I/O	33V	4/8/12/16 mA	PC0
48	31			PC1	I/O	33V	4/8/12/16 mA	PC1
49	32			PC2	I/O	33V	4/8/12/16 mA	PC2
50	33			PC3	I/O	33V	4/8/12/16 mA	PC3
51				PD7	I/O	33V	4/8/12/16 mA	PD7
52				PD8	I/O	33V	4/8/12/16 mA	PD8
53	34	25	22	PA8	I/O	33V_PU	4/8/12/16 mA	PA8_BOOT0
54	35	26	23	PA9	I/O	33V_PU	4/8/12/16 mA	PA9_BOOT1
55	36	27	24	PA10	I/O	33V	4/8/12/16 mA	PA10
56	37	28	25	PA11	I/O	33V	4/8/12/16 mA	JTDO
57	38	29	26	PA12	I/O	33V_PU	4/8/12/16 mA	JTCK/SWCLK
58	39	30	27	PA13	I/O	33V_PU	4/8/12/16 mA	JTMS/SWDIO
59	40	31	28	PA14	I/O	33V_PU	4/8/12/16 mA	JTDI
60	41	32	29	PA15	I/O	33V_PU	4/8/12/16 mA	JTRST
61	42			VDD_2	P	—	—	Voltage for digital I/O
62	43			VSS_2	P	—	—	Ground reference for digital I/O
63	44	33	30	PB0	I/O	33V	4/8/12/16 mA	PB0
64	45	34	31	PB1	I/O	33V	4/8/12/16 mA	PB1
65	46			PC4	I/O	33V	4/8/12/16 mA	PC4
66	47			PC5	I/O	33V	4/8/12/16 mA	PC5
67	48			PC6	I/O	33V	4/8/12/16 mA	PC6
68				PD9	I/O	33V	4/8/12/16 mA	PD9
69				PD10	I/O	33V	4/8/12/16 mA	PD10
70				PD11	I/O	33V	4/8/12/16 mA	PD11
71				PD12	I/O	33V	4/8/12/16 mA	PD12
72				PD13	I/O	33V	4/8/12/16 mA	PD13
73				PD14	I/O	33V	4/8/12/16 mA	PD14
74				PD15	I/O	33V	4/8/12/16 mA	PD15
75				PE0	I/O	33V	4/8/12/16 mA	PE0
		35	32	VDD_2	P	—	—	Voltage for digital I/O
		36	33	VSS_2	P	—	—	Ground reference for digital I/O
76	49	37	34	PB2	I/O	33V	4/8/12/16 mA	PB2
77	50	38	35	PB3	I/O	33V	4/8/12/16 mA	PB3
78	51	39	36	PB4	I/O	33V	4/8/12/16 mA	PB4
79	52	40	37	PB5	I/O	33V	4/8/12/16 mA	PB5



Pin Number				Pin Name	Type (1)	I/O Structure (2)	Output Driving	Description
100 LQFP	64 LQFP	48 LQFP	46 QFN					Default Function (AF0)
80	53			PC7	I/O	33V	4/8/12/16 mA	PC7
81	54			PC8	I/O	33V	4/8/12/16 mA	PC8
82				PE1	I/O	33V	4/8/12/16 mA	PE1
83				PE2	I/O	33V	4/8/12/16 mA	PE2
84				PE3	I/O	33V	4/8/12/16 mA	PE3
85	55			VDD_4	P	—	—	Voltage for digital I/O
86	56			VSS_4	P	—	—	Ground reference for digital I/O
87				PE4	I/O	33V	4/8/12/16 mA	PE4
88				PE5	I/O	33V	4/8/12/16 mA	PE5
89				PE6	I/O	33V	4/8/12/16 mA	PE6
90				PE7	I/O	33V	4/8/12/16 mA	PE7
91	57	41	38	PB6	AI/O	33V	4/8/12/16 mA	PB6
92	58	42	39	PB7	AI/O	33V	4/8/12/16 mA	PB7
93	59	43	40	PB8	AI/O	33V	4/8/12/16 mA	PB8
94	60	44	41	PB9	AI/O	33V	4/8/12/16 mA	PB9
95	61	45	42	PB10	AI/O	33V	4/8/12/16 mA	PB10
96	62	46	43	PB11	AI/O	33V	4/8/12/16 mA	PB11
97	63	47	44	VDDA	P	—	—	Analog voltage for ADC and Comparator
98	63	47	44	VREF+	P	—	—	ADC positive reference voltage has to be lower or equal to V <sub>DDA</sub>
99	64	48	45	VREF-	P	—	—	ADC negative reference voltage has to be directly connected to VSSA
100	64	48	45	VSSA	P	—	—	Ground reference for the ADC and Comparator

- Note: 1. I = Input, O = Output, A = Analog port, P = Power supply, PU = Pull-up, BK = Backup domain, EP = Exposed pad of the QFN package.  
 2. 33 V = 3.3 V tolerant.  
 3. The GPIOs are in an AF0 state after a V<sub>DD15</sub> power on reset (POR) except for the RTCOUT pin in the Backup Domain I/O. The RTCOUT pin is reset by the Backup Domain power-on-reset (PORB) or by the Backup Domain software reset (BAK\_RST bit in BAK\_CR register).  
 4. The backup domain of the I/O pins have a source current capability limitation of < 2 mA @ V<sub>DD</sub> = 3.3 V and sink current typical is 4/8 mA configurable @ V<sub>DD</sub> = 3.3 V.

# 5 Electrical Characteristics

## Absolute Maximum Ratings

The following table shows the absolute maximum ratings of the device. These are stress ratings only. Stresses beyond absolute maximum ratings may cause permanent damage to the device. Note that the device is not guaranteed to operate properly at the maximum ratings. Exposure to the absolute maximum rating conditions for extended periods may affect device reliability.

**Table 5. Absolute Maximum Ratings**

Symbol	Parameter	Min.	Max.	Unit.
V <sub>DD</sub>	External main supply voltage	V <sub>SS</sub> - 0.3	V <sub>SS</sub> + 3.6	V
V <sub>DDA</sub>	External analog supply voltage	V <sub>SSA</sub> - 0.3	V <sub>SSA</sub> + 3.6	V
V <sub>BAT</sub>	External battery supply voltage	V <sub>SS</sub> - 0.3	V <sub>SS</sub> + 3.6	V
V <sub>IN</sub>	Input voltage on other I/O	V <sub>SS</sub> - 0.3	V <sub>DD</sub> + 0.3	V
T <sub>A</sub>	Ambient operating temperature range	-40	85	°C
T <sub>STG</sub>	Storage temperature range	-55	150	°C
T <sub>J</sub>	Maximum junction temperature	—	125	°C
P <sub>D</sub>	Total power dissipation	—	500	mW
V <sub>ESD</sub>	Electrostatic discharge voltage – human body mode	-4000	4000	V

## Recommended DC Operating Conditions

**Table 6. Recommended DC Operating Conditions**

T<sub>A</sub> = 25 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V <sub>DD</sub>	I/O operating voltage	—	2.0	3.3	3.6	V
V <sub>DDA</sub>	Analog operating voltage	—	2.5	3.3	3.6	V
V <sub>BAT</sub>	Battery supply operating voltage	—	2.0	3.3	3.6	V

## On-Chip LDO Voltage Regulator Characteristics

**Table 7. LDO Characteristics**

T<sub>A</sub> = 25 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V <sub>LDO</sub>	Internal regulator output voltage	V <sub>DD</sub> ≥ 2.0 V Regulator input @ I <sub>LDO</sub> = 35 mA and voltage variant = ±5%, After trimming	1.425	1.5	1.57	V
I <sub>LDO</sub>	Output current	V <sub>DD</sub> = 2.0 V Regulator input @ V <sub>LDO</sub> = 1.5 V	—	50	75	mA
C <sub>LDO</sub>	External filter capacitor value for internal core power supply	The capacitor value is dependent on the core power current consumption	2.2	4.7	—	μF

## Power Consumption

Table 8. Power Consumption Characteristics

T<sub>A</sub> = 25 °C, unless otherwise specified.

Symbol	Parameter	f <sub>HCLK</sub>	Conditions	Min.	Typ.	Max.	Unit	
I <sub>DD</sub>	Supply current (Run mode)	96 MHz	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V HSI = 8 MHz PLL = 96 MHz	All peripherals enabled	—	51	—	mA
			All peripherals disabled	—	28	—		
		72 MHz	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V HSI = 8 MHz PLL = 72 MHz	All peripherals enabled	—	42.5	—	
				All peripherals disabled	—	24	—	
		48 MHz	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V HSI = 8 MHz PLL = 96 MHz	All peripherals enabled	—	32	—	
				All peripherals disabled	—	20	—	
		24 MHz	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V HSI = 8 MHz PLL = 96 MHz	All peripherals enabled	—	21.5	—	
				All peripherals disabled	—	12	—	
		8 MHz	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V HSI = 8 MHz PLL = off	All peripherals enabled	—	10.5	—	
				All peripherals disabled	—	5.6	—	
		1 MHz	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V HSI = 8 MHz PLL = off	All peripherals enabled	—	4.8	—	
				All peripherals disabled	—	2.7	—	
32 kHz	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V LSI = 32 kHz LDO low current mode	All peripherals enabled	—	61	—	μA		
		All peripherals disabled	—	50	—			
Supply current (Sleep mode)	96 MHz	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V HSI = 8 MHz PLL = 96 MHz MCU core sleep	All peripherals enabled	—	30	—	mA	
			All peripherals disabled	—	3.7	—		
Supply current (Deep-Sleep1 mode)	—	—	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, All clock off (HSI/PLL/f <sub>HCLK</sub> ), LDO in low power mode, LSE off, LSI on, RTC on	—	35	—	μA	
Supply current (Deep-Sleep2 mode)	—	—	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, All clock off (HSI/PLL/f <sub>HCLK</sub> ), LDO off (DMOS on), LSE off, LSI on, RTC on	—	14	—	μA	
Supply current (Power-Down mode)	—	—	V <sub>DD</sub> = V <sub>BAT</sub> = 3.3V, LDO off, LSE on, LSI on, RTC on	—	1.9	—	μA	
			V <sub>DD</sub> = V <sub>BAT</sub> = 3.3 V, LDO off, LSE off, LSI on, RTC off	—	1.7	—	μA	
I <sub>BAT</sub>	Battery supply current (Power-Down mode)	—	V <sub>DD</sub> not present, V <sub>BAT</sub> = 3.3 V, LDO off, LSE on, LSI on, RTC on	—	2.4	—	μA	
			V <sub>DD</sub> not present, V <sub>BAT</sub> = 3.3 V, LDO off, LSE off, LSI on, RTC off	—	1.5	—	μA	

- Note: 1. HSE means high speed external oscillator. HSI means 8 MHz high speed internal oscillator.  
 2. LSE means 32.768 kHz low speed external oscillator. LSI means 32 kHz low speed internal oscillator.  
 3. RTC means real time clock.  
 4. Code = while (1) { 208 NOP } executed in Flash.

## Reset and Supply Monitor Characteristics

**Table 9. V<sub>DD</sub> Power Reset Characteristics**

T<sub>A</sub> = 25 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V <sub>POR</sub>	Power on reset threshold (Rising Voltage on V <sub>DD</sub> )	T <sub>A</sub> = -40 °C ~ 85 °C	1.66	1.79	1.90	V
V <sub>PDR</sub>	Power down reset threshold (Falling Voltage on V <sub>DD</sub> )		1.49	1.64	1.78	V
V <sub>PORHYST</sub>	POR hysteresis	—	—	150	—	mV
T <sub>POR</sub>	Reset delay time	V <sub>DD</sub> = 3.3 V	—	0.1	0.2	ms

- Note: 1. Data based on characterization results only, not tested in production.  
2. Guaranteed by design, not tested in production.  
3. If the LDO will be turn on, the VDD POR has to be in the de-assertion condition. When the VDD POR is in the assertion state then the LDO will be turn off.

**Table 10. LVD/BOD Characteristics**

T<sub>A</sub> = 25 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
V <sub>BOD</sub>	Voltage of Brown Out Detection	T <sub>A</sub> = -40 °C ~ 85 °C After factory-trimmed (V <sub>DD</sub> Falling edge)	2.02	2.1	2.18	V	
V <sub>LVD</sub>	Voltage of Low Voltage Detection	T <sub>A</sub> = -40 °C ~ 85 °C (V <sub>DD</sub> Falling edge)	LVDS = 000	2.17	2.25	2.33	V
			LVDS = 001	2.32	2.4	2.48	V
			LVDS = 010	2.47	2.55	2.63	V
			LVDS = 011	2.62	2.7	2.78	V
			LVDS = 100	2.77	2.85	2.93	V
			LVDS = 101	2.92	3.0	3.08	V
			LVDS = 110	3.07	3.15	3.23	V
LVDS = 111	3.22	3.3	3.38	V			
V <sub>LVDHST</sub>	LVD hysteresis	V <sub>DD</sub> = 3.3 V	—	—	100	mV	
T <sub>SULVD</sub>	LVD Setup time	V <sub>DD</sub> = 3.3 V	—	—	5	μs	
T <sub>atLVD</sub>	LVD active delay time	V <sub>DD</sub> = 3.3 V	—	—	—	μs	
I <sub>DDLVD</sub>	Operation current <sup>(3)</sup>	V <sub>DD</sub> = 3.3 V	—	—	5	μA	

- Note: 1. Data based on characterization results only, not tested in production.  
2. Guaranteed by design, not tested in production.  
3. Bandgap current is not included.  
4. LVDS field is in PWRCU LVDCSR register.

## External Clock Characteristics

**Table 11. High Speed External Clock (HSE) Characteristics**

$T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{DD}$	Operation Range	—	2.0	—	3.6	V
$f_{HSE}$	High Speed External oscillator frequency (HSE)	—	4	—	16	MHz
$C_{LHSE}$	Load capacitance	$V_{DD} = 3.3\text{ V}$ , $R_{ESR} = 100\text{ }\Omega$ @ 16 MHz	—	—	22	pF
$R_{FHSE}$	Internal feedback resistor between XTALIN and XTALOUT pins	$V_{DD} = 3.3\text{ V}$	—	1	—	M $\Omega$
$R_{ESR}$	Equivalent Series Resistance	$V_{DD} = 3.3\text{ V}$ , $C_L = 12\text{ pF}$ @ 16 MHz, HSEDR = 0	—	—	100	$\Omega$
		$V_{DD} = 2.4\text{ V}$ , $C_L = 12\text{ pF}$ @ 16 MHz, HSEDR = 1	—	—	200	
$D_{HSE}$	HSE oscillator Duty cycle	—	40	—	60	%
$I_{DDHSE}$	HSE oscillator current consumption	$V_{DD} = 3.3\text{ V}$ $C_L = 12\text{ pF}$ HSEDR = 0	8 MHz	—	0.75	mA
			16 MHz	—	1	
$I_{PDHSE}$	HSE oscillator power down current	$V_{DD} = 3.3\text{ V}$	—	—	0.01	$\mu\text{A}$
$t_{SUHSE}$	HSE oscillator startup time	$V_{DD} = 3.3\text{ V}$ @ 8 MHz, HSEDR = 0	—	—	4	ms

**Table 12. Low Speed External Clock (LSE) Characteristics**

$T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{BAK}$	Operation Range	—	2.0	—	3.6	V
$f_{CK\_LSE}$	Frequency of LSE	$V_{BAK} = 2.0\text{ V} \sim 3.6\text{ V}$	—	32.768	—	kHz
$R_F$	Internal feedback resistor	—	—	10	—	M $\Omega$
$R_{ESR}$	Equivalent Series Resistance	$V_{BAK} = 3.3\text{ V}$	30	—	TBD	k $\Omega$
$C_L$	Recommended load capacitances	$V_{BAK} = 3.3\text{ V}$	6	—	TBD	pF
$I_{DDLSE}$	Oscillator supply current (High current mode)	$f_{CK\_LSE} = 32.768\text{ kHz}$ , $R_{ESR} = 50\text{ k}\Omega$ , $C_L \geq 7\text{ pF}$ $V_{BAK} = 2.0\text{ V} \sim 2.7\text{ V}$ , $T_A = -40\text{ }^\circ\text{C} \sim 85\text{ }^\circ\text{C}$	—	3.3	6.3	$\mu\text{A}$
	Oscillator supply current (Low current mode)	$f_{CK\_LSE} = 32.768\text{ kHz}$ , $R_{ESR} = 50\text{ k}\Omega$ , $C_L < 7\text{ pF}$ $V_{BAK} = 2.0\text{ V} \sim 3.6\text{ V}$ , $T_A = -40\text{ }^\circ\text{C} \sim 85\text{ }^\circ\text{C}$	—	1.8	3.3	$\mu\text{A}$
	Power down current	—	—	—	0.01	$\mu\text{A}$
$T_{SULSE}$	Startup time (Low current mode)	$f_{CK\_LSE} = 32.768\text{ kHz}$ , $V_{BAK} = 2.7\text{ V} \sim 3.6\text{ V}$	—	2.5	—	s

Note: The following guidelines are recommended to increase the robustness of the crystal circuit of the HSE / LSE clock in the PCB layout phase.

1. The crystal oscillator should be located as close as possible to the MCU so that the trace length would be as short as possible to reduce the parasitic capacitance.

2. Shield lines in the vicinity of the crystal by using a ground plane to isolate signals and reduce noise.
3. Keep the frequently switching signal lines away from the crystal area to prevent the crosstalk.

## Internal Clock Characteristics

**Table 13. High Speed Internal Clock (HSI) Characteristics**

$T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{DD}$	Operation Range	—	2.0	—	3.6	V
$f_{HSI}$	Frequency of HSI	$V_{DD} = 3.3\text{ V @ } 25\text{ }^\circ\text{C}$	—	8	—	MHz
$ACC_{HSI}$	Frequency accuracy of the factory-calibrated HSI oscillator	$V_{DD} = 3.3\text{ V, } T_A = 25\text{ }^\circ\text{C}$	-2	—	2	%
		$V_{DD} = 2.5\text{ V} \sim 3.6\text{ V, } T_A = -40\text{ }^\circ\text{C} \sim 85\text{ }^\circ\text{C}$	-3	—	3	%
		$V_{DD} = 2.0\text{ V} \sim 3.6\text{ V, } T_A = -40\text{ }^\circ\text{C} \sim 85\text{ }^\circ\text{C}$	-4	—	4	%
Duty	Duty cycle	$f_{HSI} = 8\text{ MHz}$	35	—	65	%
$I_{DDHSI}$	Oscillator supply current	$f_{HSI} = 8\text{ MHz}$	—	220	250	$\mu\text{A}$
	Power down current		—	—	0.05	$\mu\text{A}$
$t_{SUHSI}$	Startup time	$f_{HSI} = 8\text{ MHz}$	—	—	10	$\mu\text{s}$

**Table 14. Low Speed Internal Clock (LSI) Characteristics**

$T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$f_{LSI}$	Low Speed Internal Oscillator Frequency (LSI)	$V_{BAK} = 3.3\text{ V, } T_A = -40\text{ }^\circ\text{C} \sim 85\text{ }^\circ\text{C}$	21	32	43	kHz
$ACC_{LSI}$	Frequency accuracy of LSI	After factory-trimmed, $V_{BAK} = 3.3\text{ V, } T_A = 25\text{ }^\circ\text{C}$	-10	—	+10	%
$I_{DDL SI}$	LSI Oscillator Operating current	$V_{BAK} = 3.3\text{ V, } T_A = 25\text{ }^\circ\text{C}$	—	0.8	1.2	$\mu\text{A}$
$t_{SULSI}$	LSI Oscillator startup time	$V_{BAK} = 3.3\text{ V, } T_A = 25\text{ }^\circ\text{C}$	—	—	100	$\mu\text{s}$

## PLL Characteristics

**Table 15. PLL Characteristics**

$T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$f_{PLLIN}$	PLL input clock	—	4	—	16	MHz
$f_{CK\_PLL}$	PLL output clock	—	64	—	96	MHz
$t_{LOCK}$	PLL lock time	—	—	200	—	$\mu\text{s}$

## USB PLL Characteristics

Table 16. USB PLL Characteristics

$T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$f_{\text{PLLIN}}$	PLL input clock	—	4	—	16	MHz
$f_{\text{CK\_PLL}}$	PLL output clock	—	16	—	48	MHz
$t_{\text{LOCK}}$	PLL lock time	—	—	200	—	$\mu\text{s}$

## Memory Characteristics

Table 17. Flash Memory Characteristics

$T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$N_{\text{ENDU}}$	Number of guaranteed program/erase cycles before failure (Endurance)	$T_A = -40\text{ }^\circ\text{C} \sim 85\text{ }^\circ\text{C}$	10	—	—	K cycles
$T_{\text{RET}}$	Data retention time	$T_A = -40\text{ }^\circ\text{C} \sim 85\text{ }^\circ\text{C}$	10	—	—	Years
$t_{\text{PROG}}$	Word programming time	$T_A = -40\text{ }^\circ\text{C} \sim 85\text{ }^\circ\text{C}$	20	—	—	$\mu\text{s}$
$t_{\text{ERASE}}$	Page erase time	$T_A = -40\text{ }^\circ\text{C} \sim 85\text{ }^\circ\text{C}$	2	—	—	ms
$t_{\text{MERASE}}$	Mass erase time	$T_A = -40\text{ }^\circ\text{C} \sim 85\text{ }^\circ\text{C}$	10	—	—	ms

## I/O Port Characteristics

Table 18. I/O Port Characteristics

$T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
$I_{\text{IL}}$	Low level input current	3.3 V I/O	$V_I = V_{\text{SS}}$ , On-chip pull-up resistor disabled	—	—	3	$\mu\text{A}$
		Reset pin		—	—	3	$\mu\text{A}$
$I_{\text{IH}}$	High level input current	3.3 V I/O	$V_I = V_{\text{DD}}$ , On-chip pull-down resistor disabled	—	—	3	$\mu\text{A}$
		Reset pin		—	—	3	$\mu\text{A}$
$V_{\text{IL}}$	Low level input voltage	3.3 V I/O	—	—	$0.35 V_{\text{DD}}$	V	
		Reset pin	—	—	$0.35 V_{\text{DD}}$	V	
$V_{\text{IH}}$	High level input voltage	3.3 V I/O	$0.65 V_{\text{DD}}$	—	$V_{\text{DD}} + 0.5$	V	
		Reset pin	$0.65 V_{\text{DD}}$	—	$V_{\text{DD}} + 0.5$	V	
$V_{\text{HYS}}$	Schmitt trigger input voltage hysteresis	3.3 V I/O	—	$0.12 V_{\text{DD}}$	—	mV	
		Reset pin	—	$0.12 V_{\text{DD}}$	—	mV	

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
I <sub>OL</sub>	Low level output current (GPIO Sink current)	3.3 V I/O 4 mA drive, V <sub>OL</sub> = 0.4 V	4	—	—	mA	
		3.3 V I/O 8 mA drive, V <sub>OL</sub> = 0.4 V	8	—	—	mA	
		3.3 V I/O 12 mA drive, V <sub>OL</sub> = 0.4 V	12	—	—	mA	
		3.3 V I/O 16 mA drive, V <sub>OL</sub> = 0.4 V	16	—	—	mA	
		Backup Domain I/O drive @ V <sub>DD</sub> = 3.3 V, V <sub>OL</sub> = 0.4 V, PB10, PB11, PB12	4	—	—	mA	
I <sub>OH</sub>	High level output current (GPIO Source current)	3.3 V I/O 4 mA drive, V <sub>OH</sub> = V <sub>DD</sub> - 0.4 V	4	—	—	mA	
		3.3 V I/O 8 mA drive, V <sub>OH</sub> = V <sub>DD</sub> - 0.4 V	8	—	—	mA	
		3.3 V I/O 12 mA drive, V <sub>OH</sub> = V <sub>DD</sub> - 0.4 V	12	—	—	mA	
		3.3 V I/O 16 mA drive, V <sub>OH</sub> = V <sub>DD</sub> - 0.4 V	16	—	—	mA	
		Backup Domain I/O drive @ V <sub>DD</sub> = 3.3 V, V <sub>OL</sub> = V <sub>DD</sub> - 0.4 V, PB10, PB11, PB12.	—	—	2	mA	
V <sub>OL</sub>	Low level output voltage	3.3V 4 mA drive I/O, I <sub>OL</sub> = 4 mA	—	—	0.4	V	
		3.3V 8 mA drive I/O, I <sub>OL</sub> = 8 mA	—	—	0.4	V	
		3.3V 12 mA drive I/O, I <sub>OL</sub> = 12 mA	—	—	0.4	V	
		3.3V 16 mA drive I/O, I <sub>OL</sub> = 16 mA	—	—	0.4	V	
		Backup Domain I/O Sink Current = 4 mA (Low driving strength)	V <sub>DD</sub> = 2.7 V ~ 3.6 V	—	—	0.4	V
			V <sub>DD</sub> = 2.0 V ~ 2.7 V	—	—	0.6	V
Backup Domain I/O Sink Current = 8 mA (High driving strength)	V <sub>DD</sub> = 2.7 V ~ 3.6 V	—	—	0.4	V		
	V <sub>DD</sub> = 2.0 V ~ 2.7 V	—	—	0.6	V		
V <sub>OH</sub>	High level output voltage	3.3 V 4 mA drive I/O, I <sub>OH</sub> = 4 mA	V <sub>DD</sub> - 0.4	—	—	V	
		3.3 V 8 mA drive I/O, I <sub>OH</sub> = 8 mA	V <sub>DD</sub> - 0.4	—	—	V	
		3.3 V 12 mA drive I/O, I <sub>OL</sub> = 12 mA	V <sub>DD</sub> - 0.4	—	—	V	
		3.3 V 16 mA drive I/O, I <sub>OL</sub> = 16 mA	V <sub>DD</sub> - 0.4	—	—	V	
		Backup Domain I/O Source Current = 2 mA	V <sub>DD</sub> = 2.7 V ~ 3.6 V	2.4	—	—	V
			V <sub>DD</sub> = 2.0 V ~ 2.7 V	V <sub>DD</sub> - 0.4	—	—	V
R <sub>PU</sub>	Internal pull-up resistor	3.3 V I/O	—	46	—	kΩ	
R <sub>PD</sub>	Internal pull-down resistor	3.3 V I/O	—	46	—	kΩ	



## ADC Characteristics

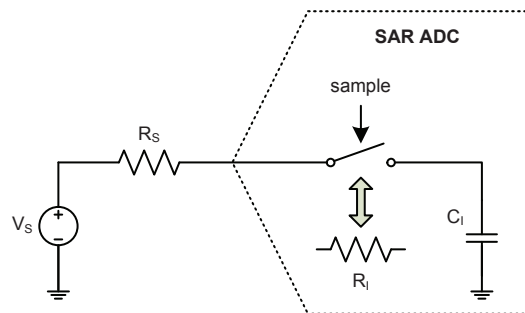
**Table 19. ADC Characteristics**

$T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{DDA}$	Operating voltage	—	2.5	3.3	3.6	V
$V_{ADCIN}$	A/D Converter input voltage range	—	0	—	$V_{REF+}$	V
$V_{REF+}$	A/D Converter Reference voltage	—	—	$V_{DDA}$	$V_{DDA}$	V
$I_{ADC}$	Current consumption	$V_{DDA} = 3.3\text{ V}$	—	0.85	1	mA
$I_{ADC\_DN}$	Power down current consumption	$V_{DDA} = 3.3\text{ V}$	—	—	0.1	$\mu\text{A}$
$f_{ADC}$	A/D Converter clock	—	0.7	—	16	MHz
$f_S$	Sampling rate	—	0.05	—	1	MHz
$T_{DL}$	Data latency	—	—	12.5	—	$1/f_{ADC}$ Cycles
$T_{S\&H}$	Sampling & hold time	—	—	3.5	—	$1/f_{ADC}$ Cycles
$T_{ADCCONV}$	A/D Converter conversion time	—	—	16	—	$1/f_{ADC}$ Cycles
$R_i$	Input sampling switch resistance	—	—	—	1	k $\Omega$
$C_i$	Input sampling capacitance	No pin/pad capacitance included	—	16	—	pF
$t_{SU}$	Startup up time	—	—	—	1	$\mu\text{s}$
N	Resolution	—	—	12	—	bits
INL	Integral Non-linearity error	$f_S = 750\text{ kHz}$ , $V_{DDA} = 3.3\text{ V}$	—	$\pm 2$	$\pm 5$	LSB
DNL	Differential Non-linearity error	$f_S = 750\text{ kHz}$ , $V_{DDA} = 3.3\text{ V}$	—	$\pm 1$	—	LSB
$E_O$	Offset error	—	—	—	$\pm 10$	LSB
$E_G$	Gain error	—	—	—	$\pm 10$	LSB

Note: 1. Guaranteed by design, not tested in production.

2. The figure below shows the equivalent circuit of the A/D Converter Sample-and-Hold input stage where  $C_i$  is the storage capacitor,  $R_i$  is the resistance of the sampling switch and  $R_S$  is the output impedance of the signal source  $V_S$ . Normally the sampling phase duration is approximately,  $3.5/f_{ADC}$ . The capacitance,  $C_i$ , must be charged within this time frame and it must be ensured that the voltage at its terminals becomes sufficiently close to  $V_S$  for accuracy. To guarantee this,  $R_S$  may not have an arbitrarily large value.



**Figure 8. ADC Sampling Network Model**

The worst case occurs when the extremities of the input range (0 V and  $V_{REF}$ ) are sampled consecutively. In this situation a sampling error below 1/4 LSB is ensured by using the following equation:

$$R_s < \frac{3.5}{f_{ADC} C_1 \ln(2^{N+2})} - R_i$$

Where  $f_{ADC}$  is the ADC clock frequency and  $N$  is the ADC resolution ( $N = 12$  in this case). A safe margin should be considered due to the pin/pad parasitic capacitances, which are not accounted for in this simple model.

If, in a system where the A/D Converter is used, there are no rail-to-rail input voltage variations between consecutive sampling phases,  $R_s$  may be larger than the value indicated by the equation above.

## Comparator Characteristics

**Table 20. Comparator Characteristics**

$T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
$V_{DDA}$	Operating voltage	Comparator mode	2.5	3.3	3.6	V	
$V_{IN}$	Input Common Mode Voltage Range	CP or CN	$V_{SSA}$	—	$V_{DDA}$	V	
$V_{IOS}$	Input offset voltage <sup>(1)</sup>	$T_A = 25\text{ }^\circ\text{C}$	-15	—	15	mV	
$V_{hys}$	Input Hysteresis	No hysteresis (CMPnHM[1:0] = 00)	Low Speed	—	0	—	mV
			High Speed	—	0	—	
		Low hysteresis (CMPnHM[1:0] = 01)	Low Speed	—	30	—	mV
			High Speed	—	30	—	
		Middle hysteresis (CMPnHM[1:0] = 10)	Low Speed	—	50	—	mV
			High Speed	—	70	—	
High hysteresis (CMPnHM[1:0] = 11)	Low Speed	—	70	—	mV		
	High Speed	—	100	—			

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
t <sub>RT</sub>	Response time Input Overdrive = ±100mV	High Speed mode	V <sub>DDA</sub> ≥ 2.7 V	—	50	100	ns
			V <sub>DDA</sub> < 2.7 V	—	100	250	
		Low Speed mode	—	2	5	μs	
I <sub>CMP</sub>	Current Consumption V <sub>DDA</sub> = 3.3 V	High Speed mode	—	180	—	μA	
		Low Speed mode	—	30	—	μA	
t <sub>CMPST</sub>	Comparator Startup Time	Comparator enabled to output valid	—	—	50	μs	
I <sub>CMP_DN</sub>	Power Down Supply Current	COMPEN = 0, CVREFEN = 0, CVREFOE = 0	—	—	0.1	μA	
<b>Comparator Voltage Reference (CVR)</b>							
V <sub>CVR</sub>	Output Range	—	V <sub>SSA</sub>	—	V <sub>DDA</sub>	V	
N <sub>Bits</sub>	CVR Scaler Resolution	—	—	6	—	bits	
t <sub>CVRST</sub>	Setting Time	CVR scaler setting time from CVREF = "000000" to "111111"	—	—	100	μs	
I <sub>CVR</sub>	Current Consumption V <sub>DDA</sub> = 3.3 V	CVREFEN = 1, CMPREFOE = 0	—	65	—	μA	
		CVREFEN = 1, CVREFOE = 1	—	80	110	μA	

Note: Guaranteed by design, not tested in production.

## GPTM/MCTM Characteristics

Table 21. GPTM/MCTM Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
f <sub>TM</sub>	Timer clock source for GPTM and MCTM	—	—	—	96	MHz
t <sub>RES</sub>	Timer resolution time	—	1	—	—	f <sub>TM</sub>
f <sub>EXT</sub>	External single frequency on channel 1 ~ 4	—	—	—	1/2	f <sub>TM</sub>
RES	Timer resolution	—	—	—	16	bits

## I<sup>2</sup>C Characteristics

Table 22. I<sup>2</sup>C Characteristics

Symbol	Parameter	Standard Mode		Fast Mode		Fast Mode Plus		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
f <sub>SCL</sub>	SCL clock frequency	—	100	—	400	—	1000	kHz
t <sub>SCL(H)</sub>	SCL clock high time	4.5	—	1.125	—	0.45	—	μs
t <sub>SCL(L)</sub>	SCL clock low time	4.5	—	1.125	—	0.45	—	μs
t <sub>FALL</sub>	SCL and SDA fall time	—	1.3	—	0.34	—	0.135	μs
t <sub>RISE</sub>	SCL and SDA rise time	—	1.3	—	0.34	—	0.135	μs
t <sub>SU(SDA)</sub>	SDA data setup time	500	—	125	—	50	—	ns
t <sub>H(SDA)</sub>	SDA data hold time	0	—	0	—	0	—	ns

Symbol	Parameter	Standard Mode		Fast Mode		Fast Mode Plus		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{SU(STA)}$	START condition setup time	500	—	125	—	50	—	ns
$t_{H(STA)}$	START condition hold time	0	—	0	—	0	—	ns
$t_{SU(STO)}$	STOP condition setup time	500	—	125	—	50	—	ns

- Note: 1. Guaranteed by design, not tested in production.  
 2. To achieve 100 kHz standard mode, the peripheral clock frequency must be higher than 2 MHz.  
 3. To achieve 400 kHz fast mode, the peripheral clock frequency must be higher than 8 MHz.  
 4. To achieve 1 MHz fast mode plus, the peripheral clock frequency must be higher than 20 MHz.  
 5. The above characteristic parameters of the I<sup>2</sup>C bus timing are based on: SEQ\_FILTER = 01 and COMB\_FILTER\_En is disabled.

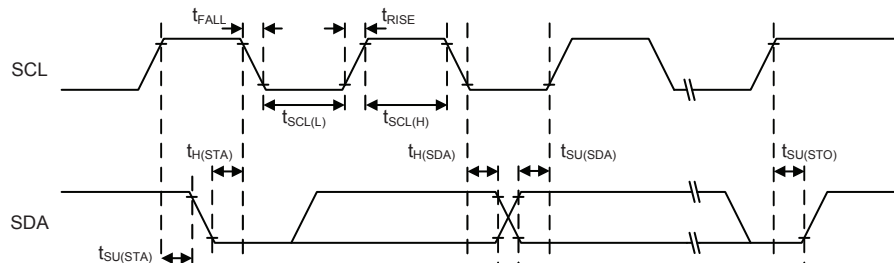


Figure 9. I<sup>2</sup>C Timing Diagrams

## SPI Characteristics

Table 23. SPI Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>SPI Master mode</b>						
$f_{SCK}$ ( $1/t_{SCK}$ )	SPI master output SCK clock frequency	Master mode SPI peripheral clock frequency $f_{PCLK}$	—	—	$f_{PCLK}/2$	MHz
$t_{SCK(H)}$ $t_{SCK(L)}$	SCK clock high and low time	—	$t_{SCK}/2 - 2$	—	$t_{SCK}/2 + 1$	ns
$t_{V(MO)}$	Data output valid time	—	—	—	5	ns
$t_{H(MO)}$	Data output hold time	—	2	—	—	ns
$t_{SU(MI)}$	Data input setup time	—	5	—	—	ns
$t_{H(MI)}$	Data input hold time	—	5	—	—	ns
<b>SPI Slave mode</b>						
$f_{SCK}$ ( $1/t_{SCK}$ )	SPI slave input SCK clock frequency	Slave mode SPI peripheral clock frequency $f_{PCLK}$	—	—	$f_{PCLK}/3$	MHz
Duty <sub>SCK</sub>	SPI slave input SCK clock duty cycle	—	30	—	70	%
$t_{SU(SEL)}$	SEL enable setup time	—	$3 \times t_{PCLK}$	—	—	ns
$t_{H(SEL)}$	SEL enable hold time	—	$2 \times t_{PCLK}$	—	—	ns

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$t_{A(SO)}$	Data output access time	—	—	—	$3 \times t_{PCLK}$	ns
$t_{DIS(SO)}$	Data output disable time	—	—	—	10	ns
$t_{V(SO)}$	Data output valid time	—	—	—	25	ns
$t_{H(SO)}$	Data output hold time	—	15	—	—	ns
$t_{SU(SI)}$	Data input setup time	—	5	—	—	ns
$t_{H(SI)}$	Data input hold time	—	4	—	—	ns

Note:  $t_{SCK} = 1/f_{SCK}$ ;  $t_{PCLK} = 1/f_{PCLK}$ . SPI output (input) clock frequency  $f_{SCK}$ ; SPI peripheral clock frequency  $f_{PCLK}$ .

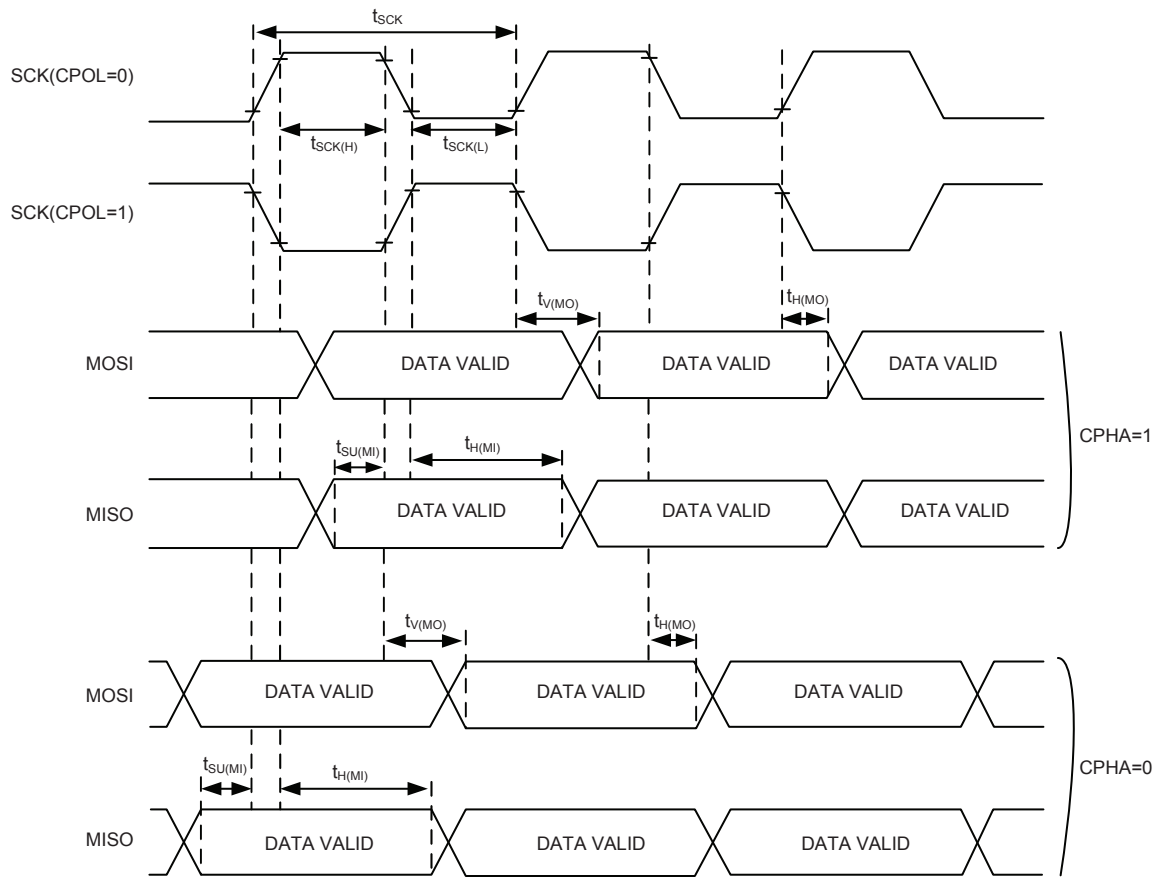


Figure 10. SPI Timing Diagrams – SPI Master Mode

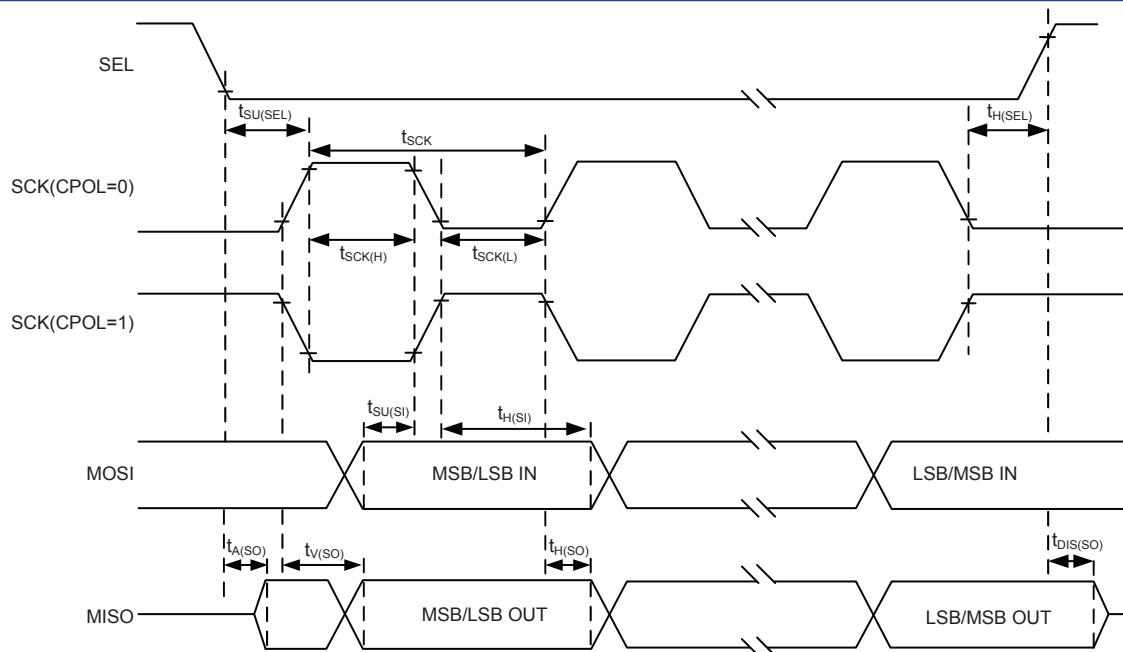


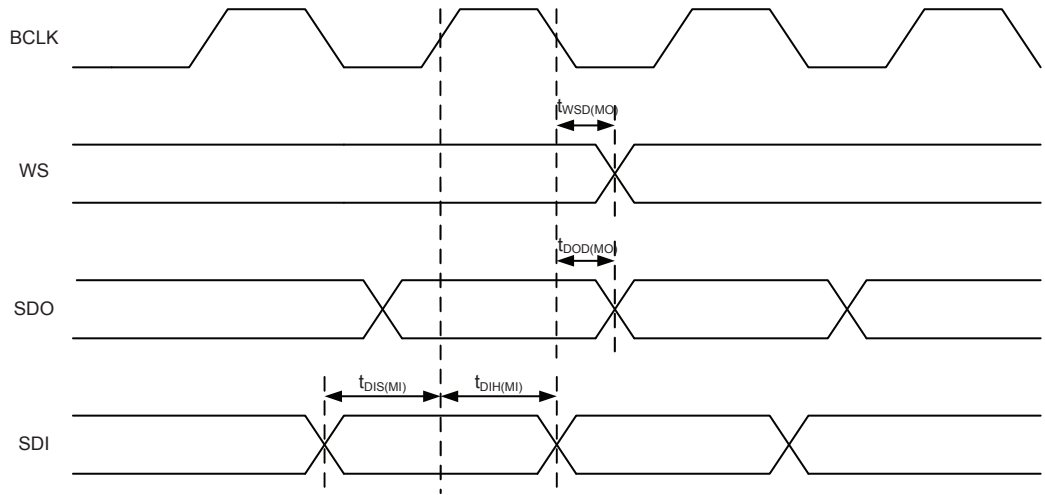
Figure 11. SPI Timing Diagrams – SPI Slave Mode with CPHA=1

## I<sup>2</sup>S Characteristics

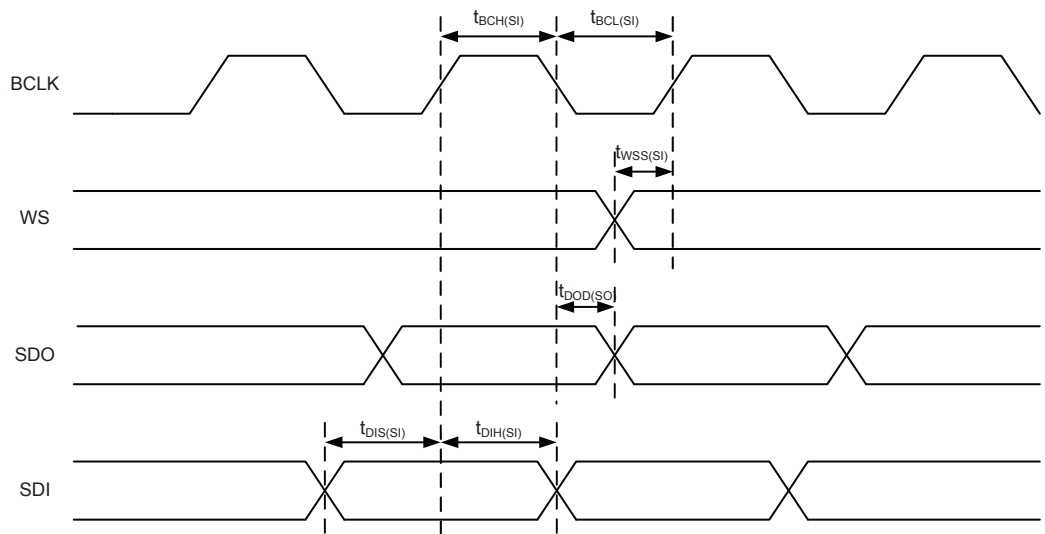
Table 24. I<sup>2</sup>S Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>I<sup>2</sup>S Master mode</b>						
t <sub>WSD(MO)</sub>	WS output to BCLK delay	—	0	—	4.6	ns
t <sub>DOD(MO)</sub>	Data output to BCLK delay	—	0.5	—	5.4	ns
t <sub>DIS(MI)</sub>	Data input setup time	—	0	—	—	ns
t <sub>DIH(MI)</sub>	Data input hold time	—	13	—	—	ns
<b>I<sup>2</sup>S Slave mode</b>						
t <sub>BCH(SI)</sub>	BCLK high pulse width	—	42	—	—	ns
t <sub>BCL(SI)</sub>	BCLK low pulse width	—	42	—	—	ns
t <sub>WSS(SI)</sub>	WS input setup time	—	0	—	—	ns
t <sub>DOD(SO)</sub>	Data output to BCLK delay	—	—	—	9	ns
t <sub>DIS(SI)</sub>	Data input setup time	—	0	—	—	ns
t <sub>DIH(SI)</sub>	Data input hold time	—	2.1	—	—	ns

- Note: 1. Guaranteed by characterization results, not tested in production.  
 2. I/O driving current is set to 4 mA.  
 3. Capacitive load C = 10 pF, V<sub>DD</sub> = 3.3 V and ambient temperature T<sub>A</sub> = 25 °C.  
 4. Measurement points are set at CMOS levels = 0.5 V<sub>DD</sub>.



**Figure 12. Timing of I<sup>2</sup>S Master Mode**



**Figure 13. Timing of I<sup>2</sup>S Slave Mode**

## SDIO Characteristics

Table 25. SDIO Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$f_{SDCK}$	Clock frequency in data transfer mode	—	—	—	48	MHz
$t_{W(CKL)}$	Clock low time	$f_{SDCK} = 48$ MHz	—	9	—	ns
$t_{W(CKH)}$	Clock high time	$f_{SDCK} = 48$ MHz	—	10	—	ns
<b>CMD, Data inputs referenced to SD_CLK in SD default mode</b>						
$t_{ISU(SD)}$	Input setup time SD default mode	$f_{SDCK} = 24$ MHz	3	—	—	ns
$t_{IH(SD)}$	Input hold time SD default mode	$f_{SDCK} = 24$ MHz	0	—	—	ns
<b>CMD, Data outputs referenced to SD_CLK in SD default mode</b>						
$t_{OV(SD)}$	Output valid time SD default mode	$f_{SDCK} = 24$ MHz	—	5	7	ns
$t_{OH(SD)}$	Output hold time SD default mode	$f_{SDCK} = 24$ MHz	2	—	—	ns
<b>CMD, Data inputs referenced to SD_CLK in SD HS mode</b>						
$t_{ISU(HS)}$	Input setup time SD HS mode	$f_{SDCK} = 48$ MHz	2	—	—	ns
$t_{IH(HS)}$	Input hold time SD HS mode	$f_{SDCK} = 48$ MHz	0.5	—	—	ns
<b>CMD, Data outputs referenced to SD_CLK in SD HS mode</b>						
$t_{OV(HS)}$	Output valid time SD HS mode	$f_{SDCK} = 48$ MHz	—	6.5	8	ns
$t_{OH(HS)}$	Output hold time SD HS mode	$f_{SDCK} = 48$ MHz	1.5	—	—	ns

- Note: 1. Guaranteed by characterization results, not tested in production.  
 2. I/O driving current is set to 16 mA.  
 3. Capacitive load  $C = 30$  pF,  $V_{DD} = 3.3$  V and ambient temperature  $T_A = 25$  °C.  
 4. Measurement points are set at CMOS levels =  $0.5 V_{DD}$ .

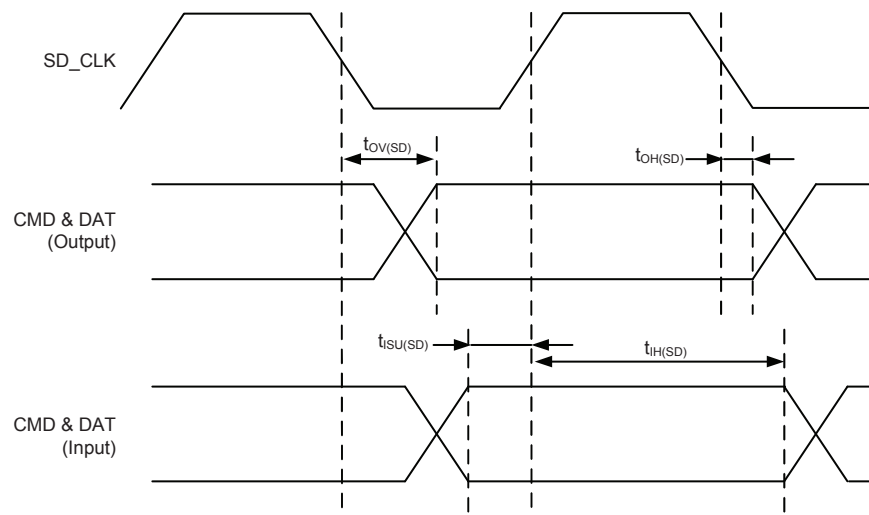


Figure 14. SDIO Default Mode



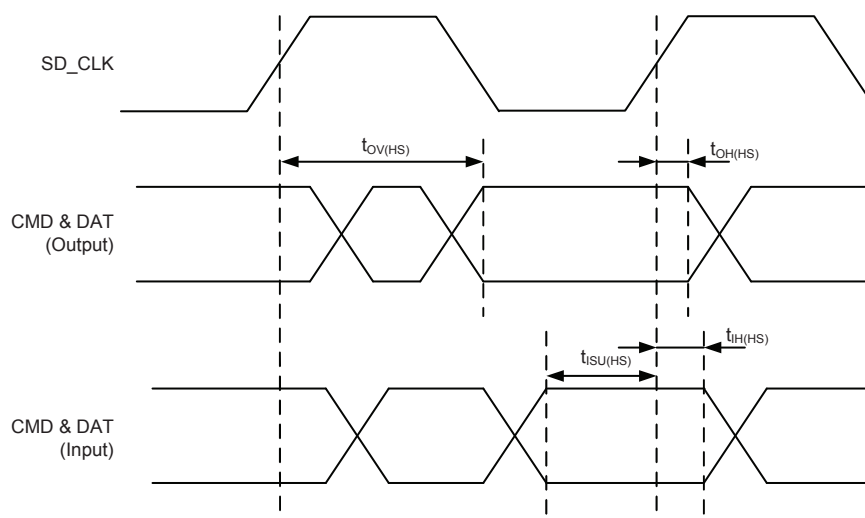


Figure 15. SDIO High-speed Mode

## CSIF Characteristics

Table 26. CSIF Electrical Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$f_{MCK}$	CSIF_MCK clock frequency output	—	—	—	48	MHz
$f_{PCK}$	CSIF_PCK clock frequency input	—	—	—	32	MHz
$r_F$	AHB clock and CSIF_PCK clock input frequency ratio	$f_{PCLK}/f_{CSIF\_PCK}$	—	—	3	

## USB Characteristics

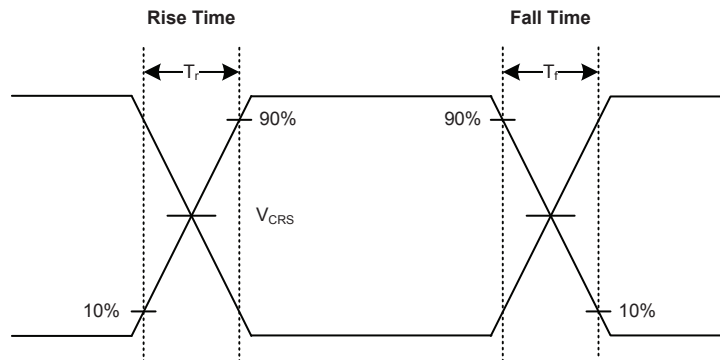
The USB interface is USB-IF certified – Full Speed.

Table 27. USB DC Electrical Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{DD}$	USB operating voltage	—	3.0	—	3.6	V
$V_{DI}$	Differential input sensitivity	$ USBDP - USBDM $	0.2	—	—	V
$V_{CM}$	Common mode voltage range	—	0.8	—	2.5	V
$V_{SE}$	Single-ended receiver threshold	—	0.8	—	2.0	V
$V_{OL}$	Pad output low voltage	$R_L$ of 1.5 k $\Omega$ to $V_{DD}$	0	—	0.3	V
$V_{OH}$	Pad output high voltage		2.8	—	3.6	V
$V_{CRS}$	Differential output signal cross-point voltage		1.3	—	2.0	V
$Z_{DRV}$	Driver output resistance	—	—	10	—	$\Omega$

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$C_{IN}$	Transceiver pad capacitance	—	—	—	20	pF

- Note: 1. Guaranteed by design, not tested in production.  
 2. The USB functionality is ensured down to 2.7 V but not the full USB electrical characteristics which will experience degradation in the 2.7 V to 3.0 V voltage range.  
 3.  $R_L$  is the internal resistor load connected to the USB driver USBDP.



**Figure 16. USB Signal Rise Time and Fall Time and Cross-Point Voltage ( $V_{CRS}$ ) Definition**

**Table 28. USB AC Electrical Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$T_r$	Rise time	$C_L = 50 \text{ pF}$	4	—	20	ns
$T_f$	Fall time	$C_L = 50 \text{ pF}$	4	—	20	ns
$T_{r/f}$	Rise time / fall time matching	$T_{r/f} = T_r / T_f$	90	—	110	%

## 6 Package Information

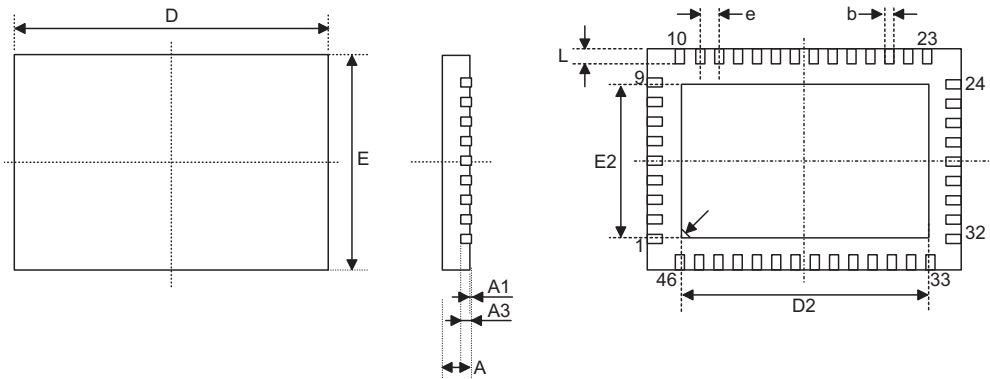
---

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the [Holtek website](#) for the latest version of the [Package/Carton Information](#).

Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

- [Package Information \(include Outline Dimensions, Product Tape and Reel Specifications\)](#)
- [The Operation Instruction of Packing Materials](#)
- [Carton information](#)

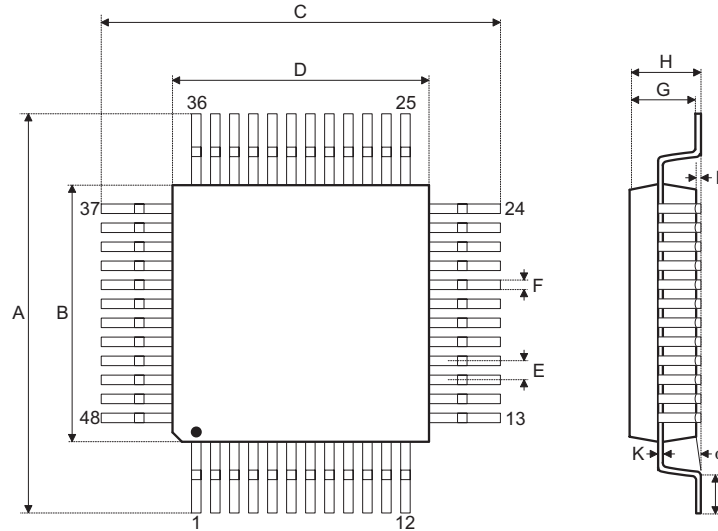
## SAW Type 46-pin (6.5mm×4.5mm) QFN Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.031	0.033	0.035
A1	0.000	0.001	0.002
A3	—	0.008 BSC	—
b	0.006	0.008	0.010
D	0.254	0.256	0.258
E	0.175	0.177	0.179
e	—	0.016 BSC	—
D2	0.197	0.201	0.205
E2	0.118	0.122	0.126
L	0.012	0.016	0.020

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	0.80	0.85	0.90
A1	0.00	0.02	0.04
A3	—	0.20 BSC	—
b	0.15	0.20	0.25
D	6.45	6.50	6.55
E	4.45	4.50	4.55
e	—	0.40 BSC	—
D2	5.00	5.10	5.20
E2	3.00	3.10	3.20
L	0.30	0.40	0.50

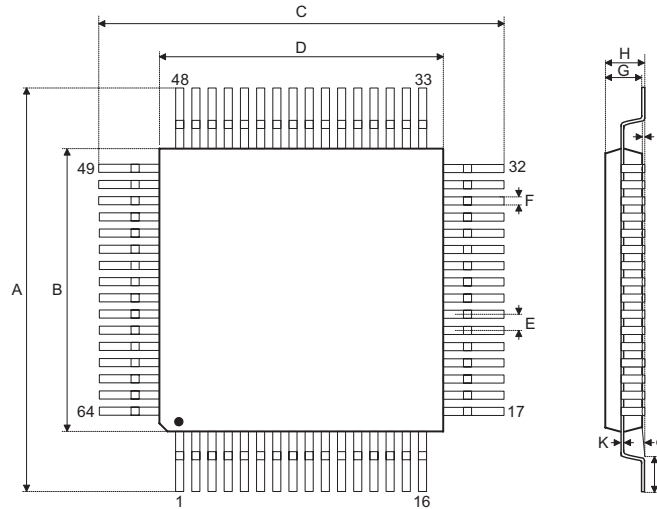
### 48-pin LQFP (7mm×7mm) Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.354 BSC	—
B	—	0.276 BSC	—
C	—	0.354 BSC	—
D	—	0.276 BSC	—
E	—	0.020 BSC	—
F	0.007	0.009	0.011
G	0.053	0.055	0.057
H	—	—	0.063
I	0.002	—	0.006
J	0.018	0.024	0.030
K	0.004	—	0.008
α	0°	—	7°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	9.0 BSC	—
B	—	7.0 BSC	—
C	—	9.0 BSC	—
D	—	7.0 BSC	—
E	—	0.5 BSC	—
F	0.17	0.22	0.27
G	1.35	1.4	1.45
H	—	—	1.60
I	0.05	—	0.15
J	0.45	0.60	0.75
K	0.09	—	0.20
α	0°	—	7°

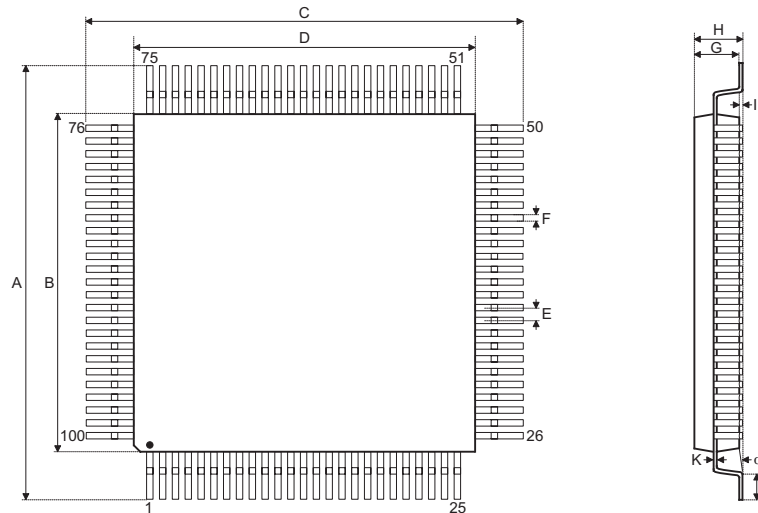
## 64-pin LQFP (7mm×7mm) Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.354 BSC	—
B	—	0.276 BSC	—
C	—	0.354 BSC	—
D	—	0.276 BSC	—
E	—	0.016 BSC	—
F	0.005	0.007	0.009
G	0.053	0.055	0.057
H	—	—	0.063
I	0.002	—	0.006
J	0.018	0.024	0.030
K	0.004	—	0.008
$\alpha$	0°	—	7°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	9.00 BSC	—
B	—	7.00 BSC	—
C	—	9.00 BSC	—
D	—	7.00 BSC	—
E	—	0.40 BSC	—
F	0.13	0.18	0.23
G	1.35	1.40	1.45
H	—	—	1.60
I	0.05	—	0.15
J	0.45	0.60	0.75
K	0.09	—	0.20
$\alpha$	0°	—	7°

## 100-pin LQFP (14mm×14mm) Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.630 BSC	—
B	—	0.551 BSC	—
C	—	0.630 BSC	—
D	—	0.551 BSC	—
E	—	0.020 BSC	—
F	0.007	0.009	0.011
G	0.053	0.055	0.057
H	—	—	0.063
I	0.002	—	0.006
J	0.018	0.024	0.030
K	0.004	—	0.008
α	0°	—	7°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	16.00 BSC	—
B	—	14.00 BSC	—
C	—	16.00 BSC	—
D	—	14.00 BSC	—
E	—	0.50 BSC	—
F	0.17	0.22	0.27
G	1.35	1.40	1.45
H	—	—	1.60
I	0.05	—	0.15
J	0.45	0.60	0.75
K	0.09	—	0.20
α	0°	—	7°

Copyright© 2017 by HOLTEK SEMICONDUCTOR INC.

The information appearing in this Data Sheet is believed to be accurate at the time of publication. However, Holtek assumes no responsibility arising from the use of the specifications described. The applications mentioned herein are used solely for the purpose of illustration and Holtek makes no warranty or representation that such applications will be suitable without further modification, nor recommends the use of its products for application that may present a risk to human life due to malfunction or otherwise. Holtek's products are not authorized for use as critical components in life support devices or systems. Holtek reserves the right to alter its products without prior notification. For the most up-to-date information, please visit our web site at <http://www.holtek.com/en/>.